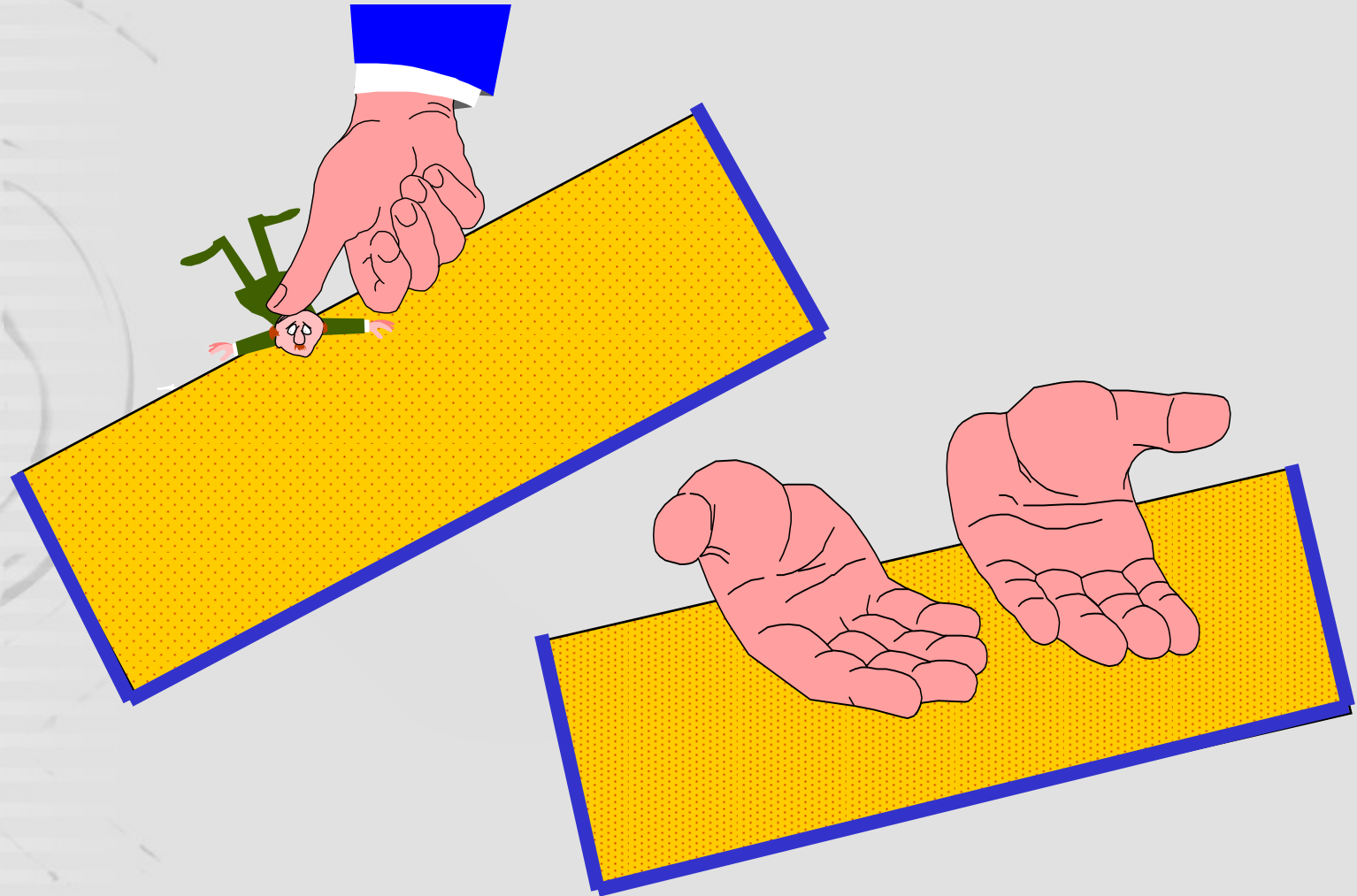
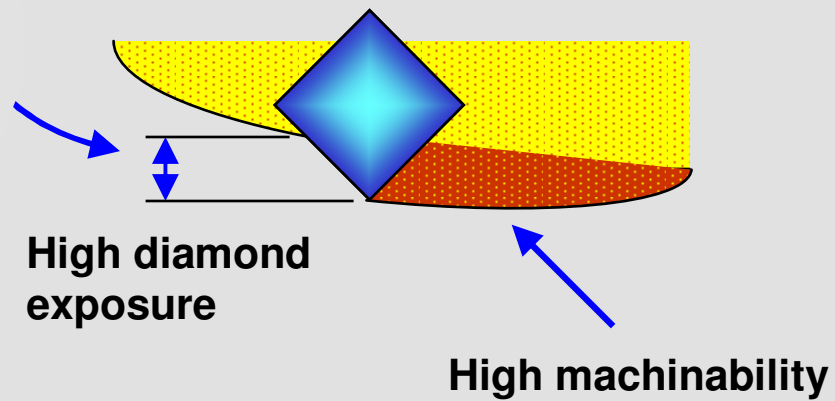
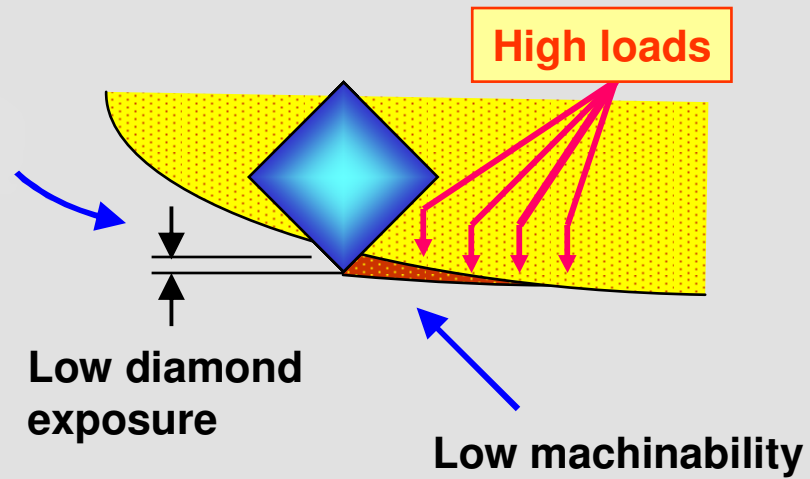




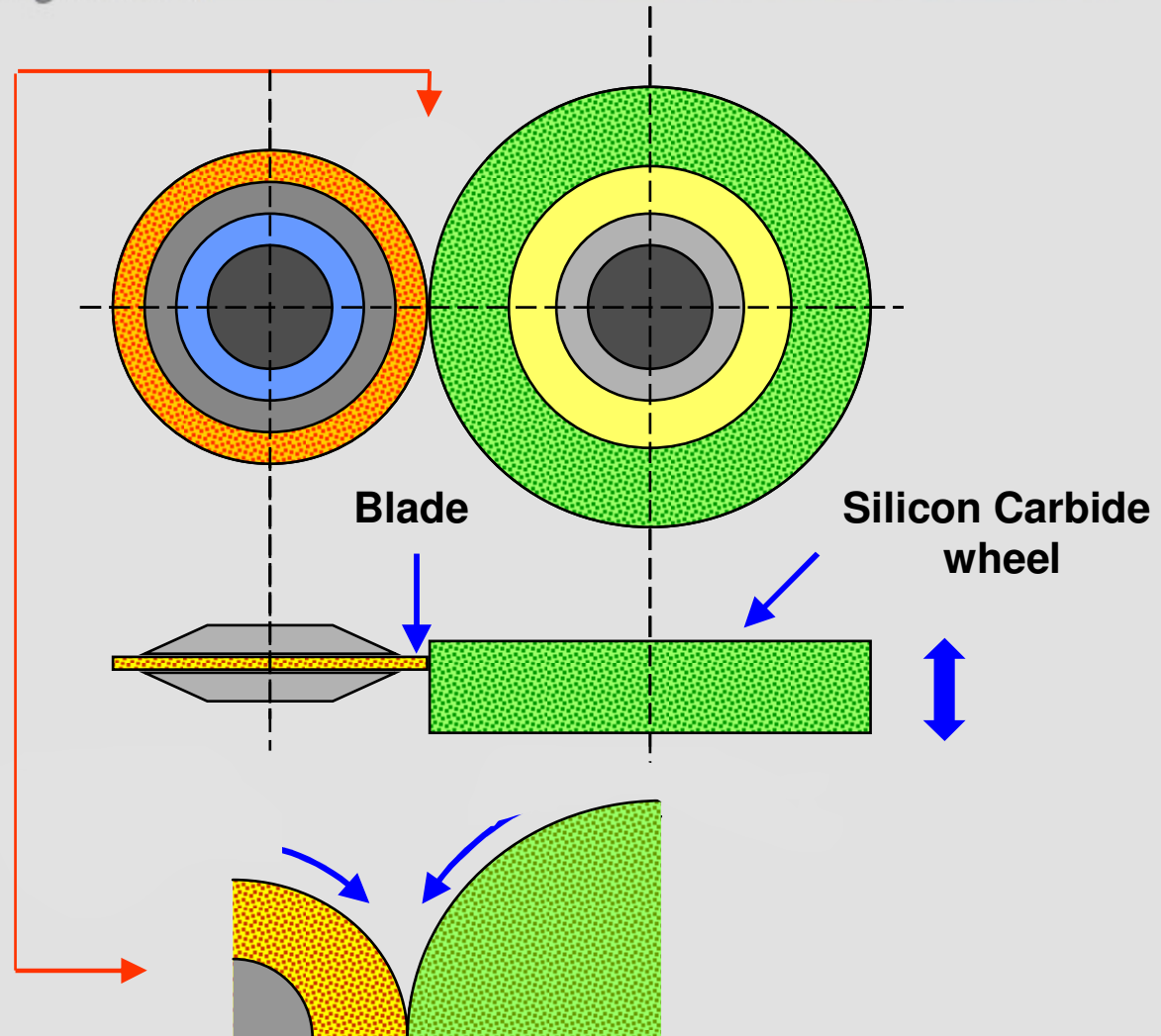
Pushing and Entering



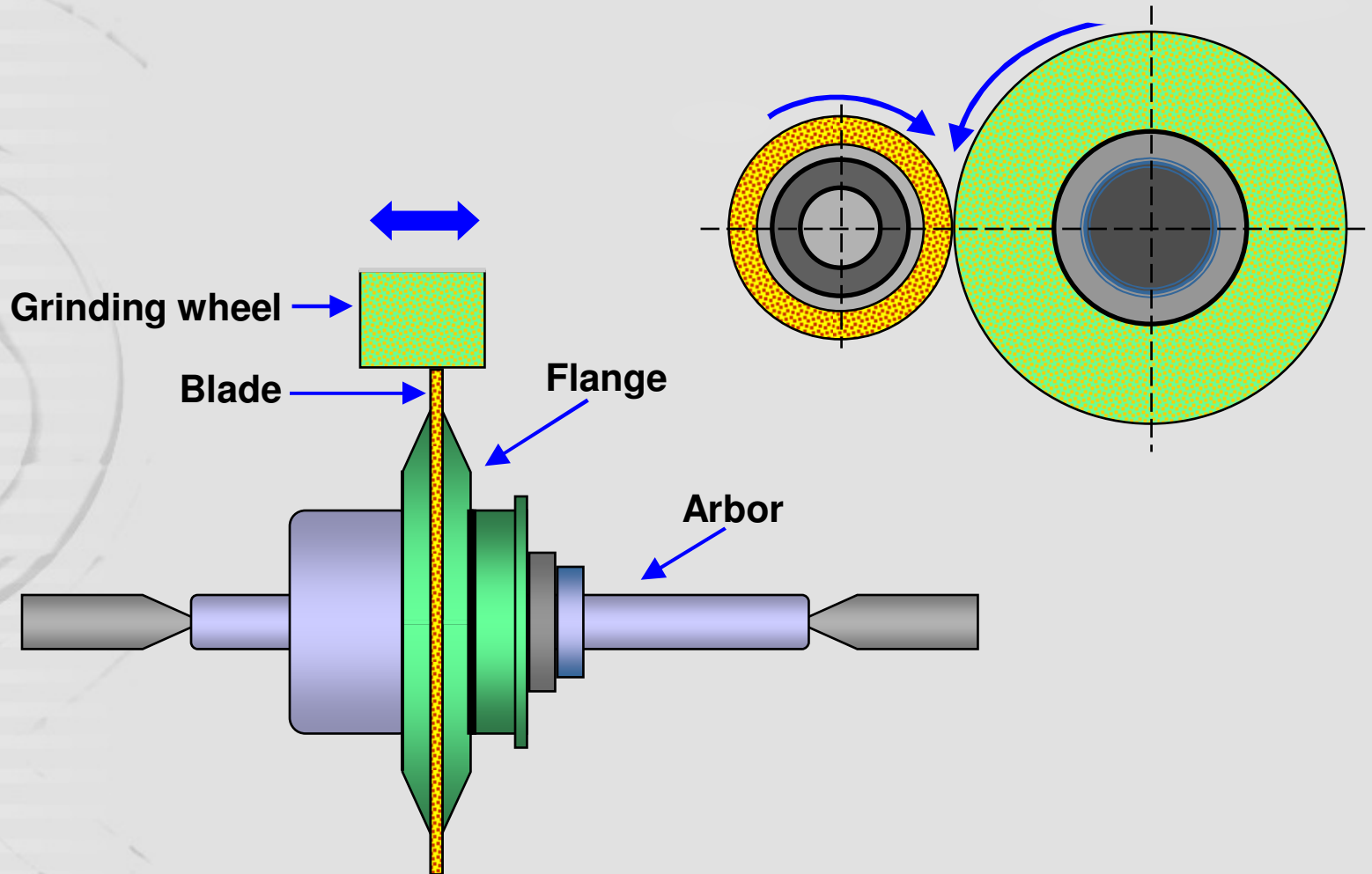
Dressed Blades versus Non Dressed Blades



Blade Edge Grinding



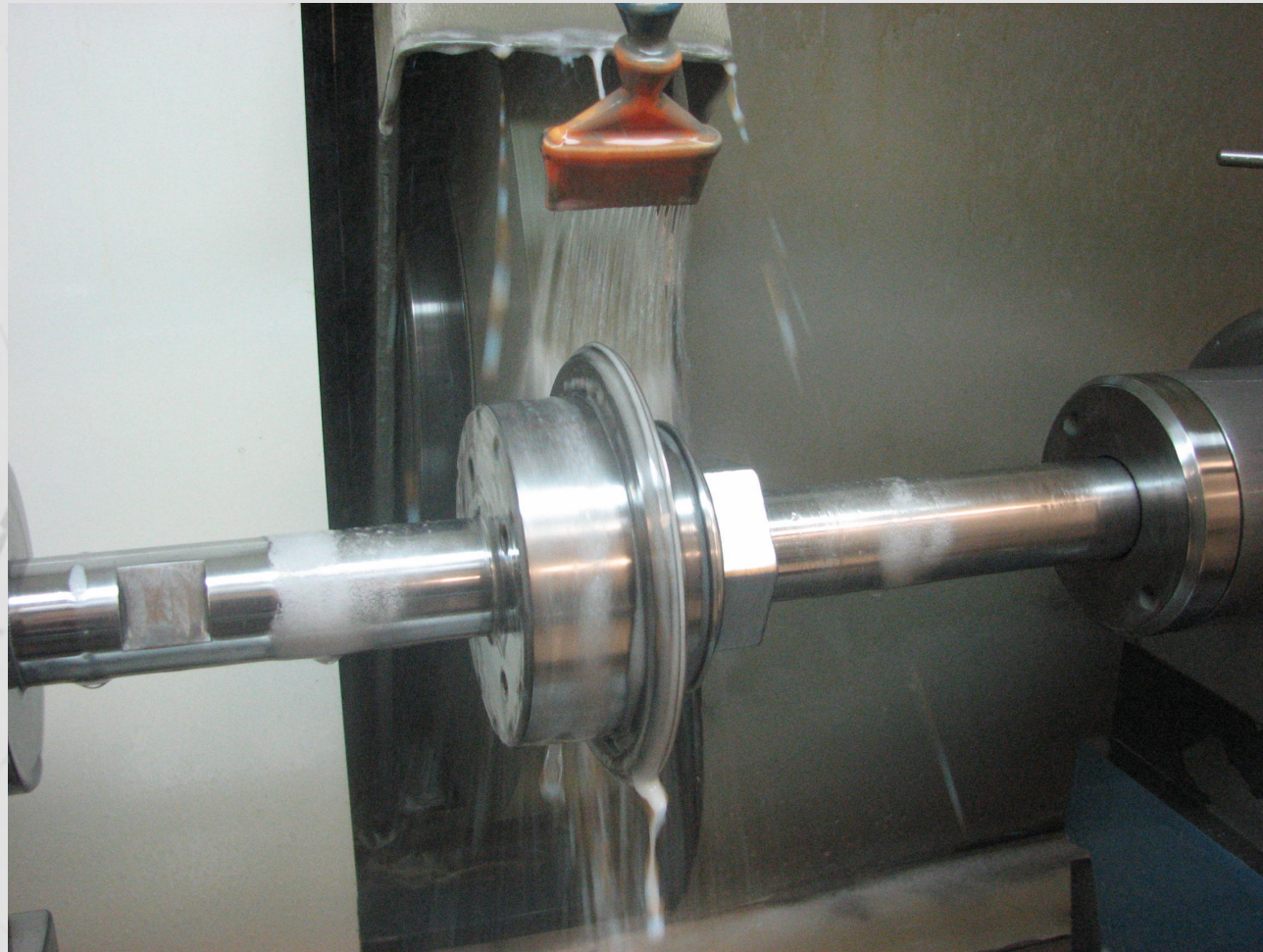
O.D. Grinding



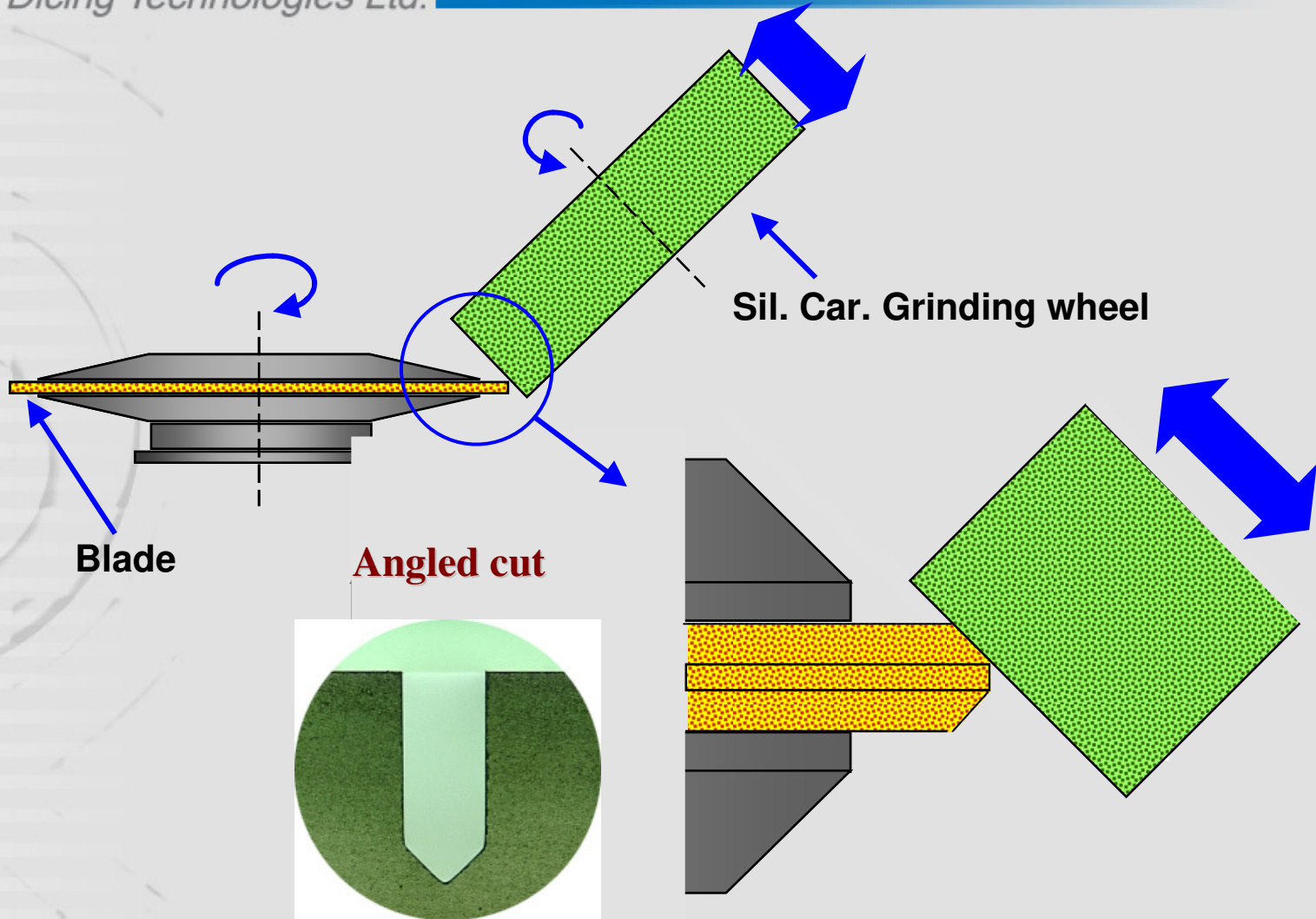


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O.D. Grinding



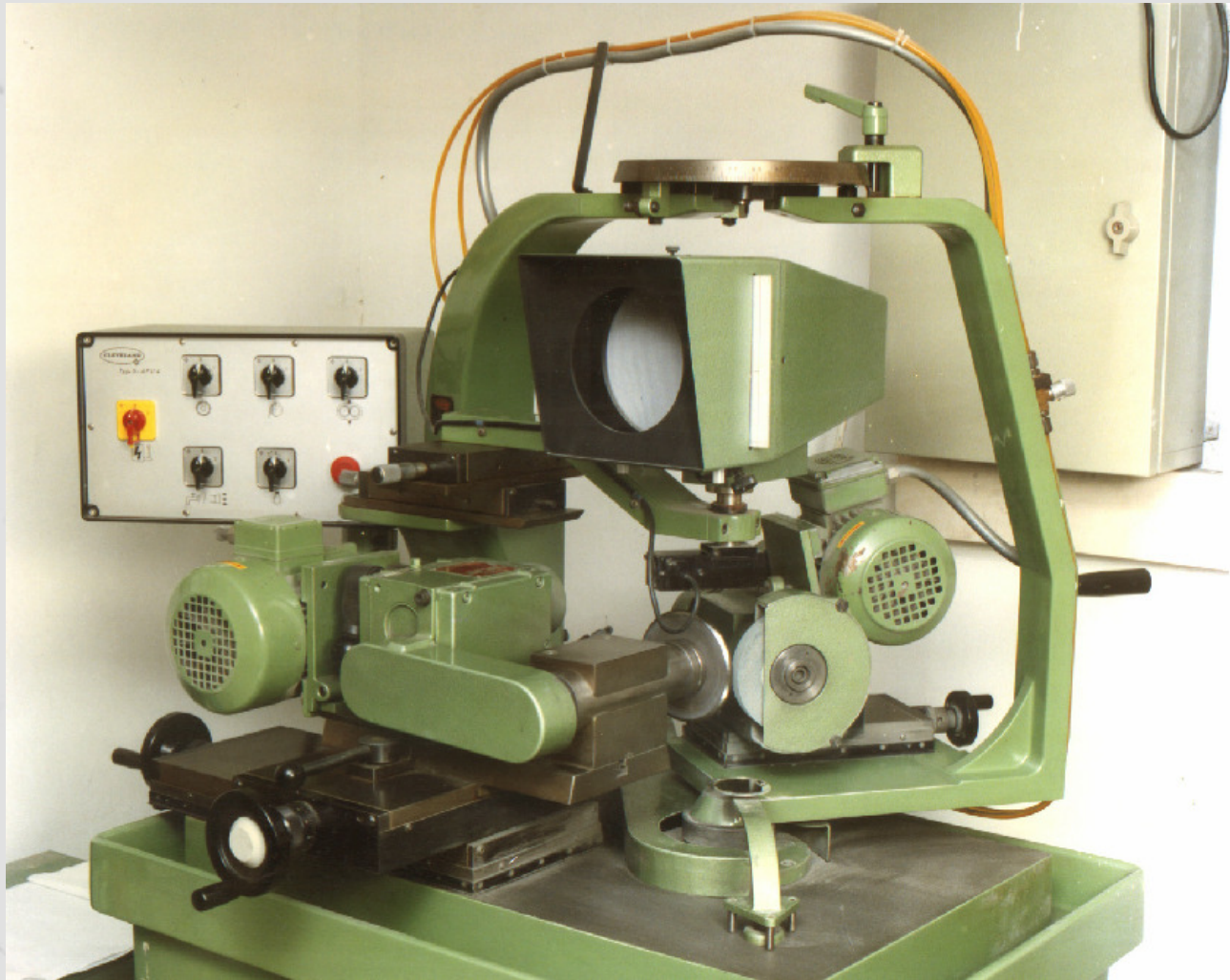
Profile Grinding





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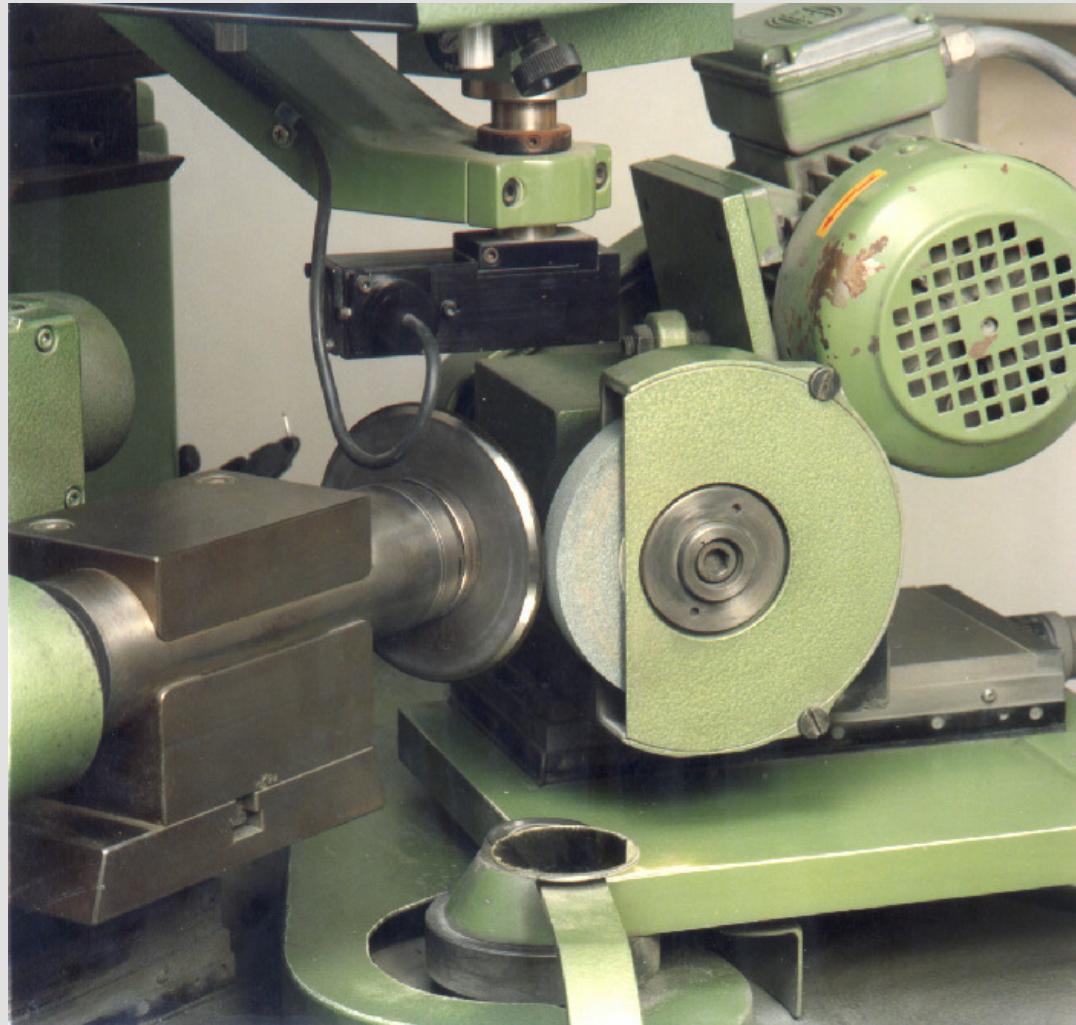
Dressing Machine

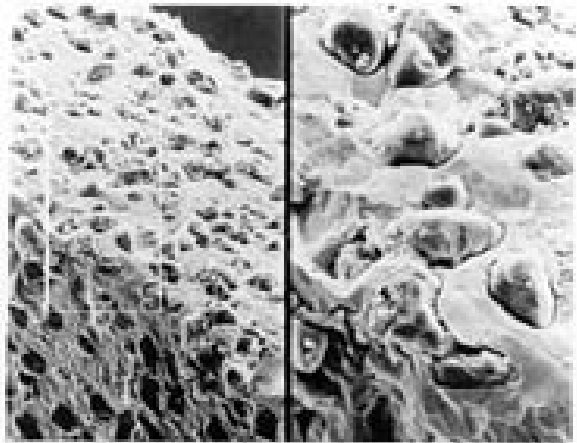




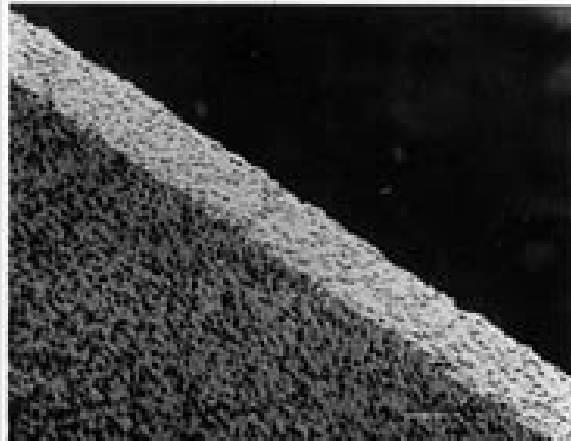
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Dressing Machine





**Nickel blade
17mic. Grit - 330x / 1000x
after Electropolishing**



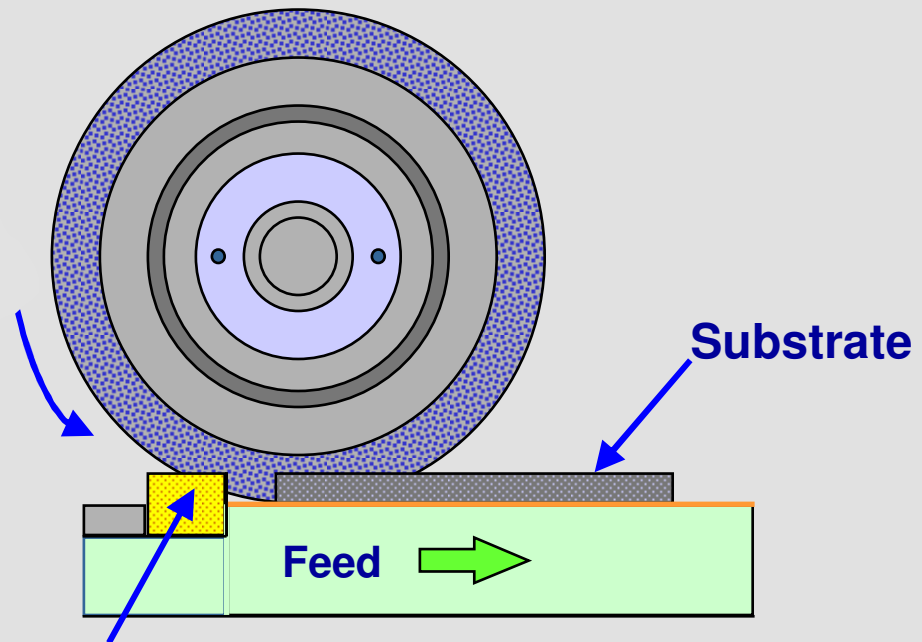
**Nickel blade
17mic. Grit - 100x
after Electropolishing**



**Nickel blade
17mic. Grit - 100x
After fine grinding
with a Si. Ca. wheel**

On Line Dressing

- ★ After each cut the blades is passing a dressing media.



**Sil. Carbide or Al. Oxide
Dressing Stick.**



Recommended dressing Procedure for Nickel Blades up to .003" thick

On a Sil. Carbide dressing block: - ADT P/N – 767- 000 - 001

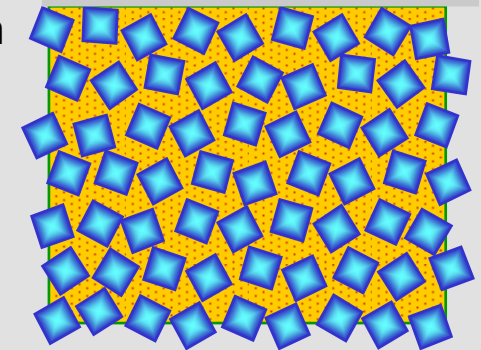
- 10x cuts .002" deep at 6" / sec.
- 10x cuts .002" deeper than production depth at .2"/sec.
- 10x cuts .002" deeper than production depth at .5"/sec.

On a blank Sil. wafer or on a production wafer:

- 10x cuts .001" deeper than production depth at .1"/sec.
- Continue with .2"/sec steps 10-20x cuts depending on cut quality up to production speed.

Hub blades recommended dressing procedure:

- On a sil. Wafer 10-20 cuts at .5"/sec and gradually increasing the feed rate depending on kerf quality up to production speed



Spindle speed:

2" blades - 30-40Krpm

4" blades - 14-16Krpm



Recommended dressing Procedure for Nickel Blades Over .003" thick

On a Sil. Carbide dressing block:

- 20x cuts .002" deep at 6"/sec.
- 10x cuts .020" deep at .5"/sec
- Make a height calibration on the saw
- 10-20x cuts .001" - .002" deep at 1"/sec

On a production substrate:

- Depending on the material being diced, start at min. feed rate and at production depth. Increase the feed rate every 10-20x cuts depending on kerf quality up to production speed

Spindle speeds:

- 2" blade - 25-35Krpm
- 3" blade - 15-25Krpm
- 4" blades - 10-15Krpm



Recommended dressing Procedure for Pre Dressed Nickel blades Over .005" Thick

Pre dressed nickel blades are grounded on the edge to get a 90° flat edge and to expose the diamonds.

For best results, to minimize the load on the blade and get better cut quality, the following is recommended before production cuts.

- On a Sil. Carbide dressing block, make 20-30x cuts at .0005" - .001" cut depth and 1"/sec. Feed rate.**

Spindle speed:

2" blades - 25-30Krpm

3" blades - 15-24Krpm

4" blades - 10-15Krpm



BGA - Recommended Dressing Procedure for Nickel Blades 30, 50 & 70mic. Grit

Follow this procedure to achieve the best cutting results, by dressing the blade on the dicing saw:

New (unused) blade:

A. Dressing the blade edge:

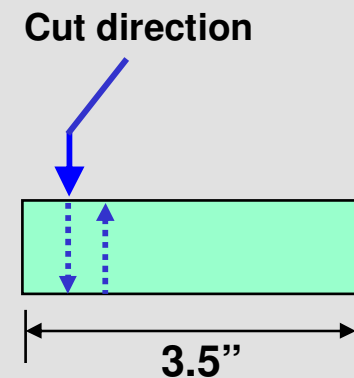
- 1) Dressing block - Sil. Car. 320 mesh ADT P/N 767--320-001
3.5" x 1" x 3/16" (88.9 x 25.4 x 4.8mm)

A 3mm thickness block is also available -
ADT P/N 767-0320-001-030

- 2) Spindle speed 5Krpm
- 3) Cutting speed - 4"/sec (100mm/sec.)
- 4) Cut depth - .005" (0.13)mm)

Measure and set the dressing block thickness on each new dressing block prior to setting the .005" cut depth.

- 5) cut mode -scribe (cutting both directions)
 - 6) Index - equal to blade thickness.
 - 7) Number of cuts - to cut the entire length of the dressing block (3.5" / index)
- ***Do not perform "height" on the saw during this dressing***





BGA - Recommended Dressing Procedure for Nickel Blades 30, 50 & 70mic. Grit

Cont.

B. Dressing the blade edge & side surface:

- 1) Dressing block - Same as above.
- 2) Spindle speed - 2" blades - 20Krpm. 3" blades 15Krpm
- 3) Cutting speed - 1"/sec (25mm/sec)
- 4) Cut depth - .004" - (0.1mm) deeper than production depth
- 5) Cut mode - Dice
- 6) Index - .040" (1mm)
- 7) Number of cuts - 4x

C. In process dressing (After production overloading):

- 1) Dressing block - same.
- 2) Spindle speed - 5K
- 3) Cutting speed - 1"/sec (25mm/sec)
- 4) Cut depth - .004" (0.1mm) deeper than production depth
- 5) Cut mode - Dice
- 6) Index - .040" (1mm)
- 7) Number of cuts - 6-8x

BGA - Recommended Dressing Procedure for Metal Sintered Blades 30, 50 & 70mic. Grit

Follow this procedure to achieve the best cutting results, by dressing the blade on the dicing saw:

New (unused) blade:

A. Dressing the blade edge:

- 1) Dressing block - Sil. Car. 320 mesh ADT P/N 767--320-001
3.5" x 1" x 3/16" (88.9 x 25.4 x 4.8mm)

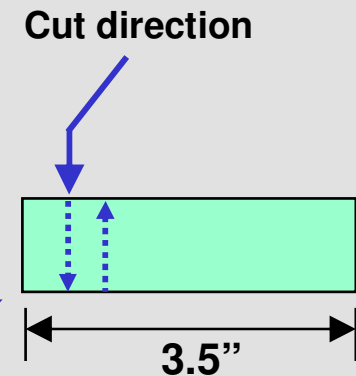
A 3mm thickness block is also available -
ADT P/N 767-0320-001-030

- 2) Spindle speed 5Krpm
- 3) Cutting speed - 4"/sec (100mm/sec.)
- 4) Cut depth - .003" (0.076)mm

Measure and set the dressing block thickness on each new dressing block prior to setting the .003" cut depth.

- 5) cut mode -scribe (cutting both directions)
- 6) Index - equal to blade thickness.
- 7) Number of cuts - 40x

Do not perform "height" on the saw during this dressing





BGA - Recommended Dressing Procedure for Metal Sintered Blades 30, 50 & 70mic. Grit

Cont.

B. Dressing the blade edge & side surfaces:

- 1) Dressing block - Same as above.
- 2) Spindle speed - 2" blades - 20Krpm. 3" blades 15Krpm
- 3) Cutting speed - .5"/sec (13 mm/sec)
- 4) Cut depth - .002" - (0.05mm) deeper than production depth
- 5) Cut mode - Dice
- 6) Index - .040" (1mm)
- 7) Number of cuts - 4x

Perform a height calibration prior to dicing production wafers

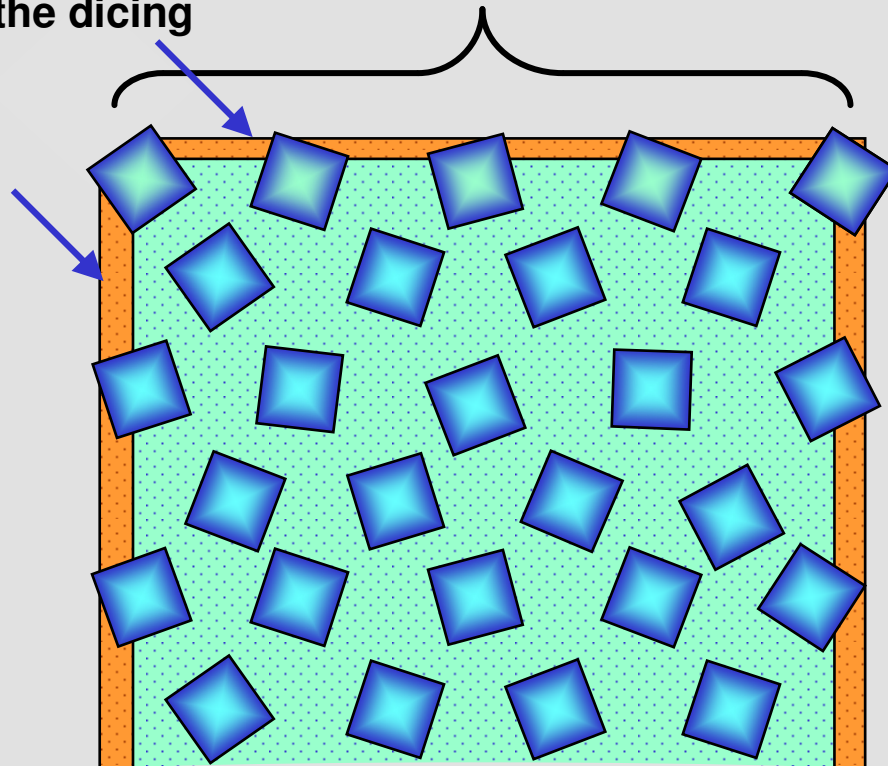
Remark:

The above dressing procedure should be optimized per each application

Re - Dressing During the Cutting Process

Powder residue
from the dicing

Blade edge

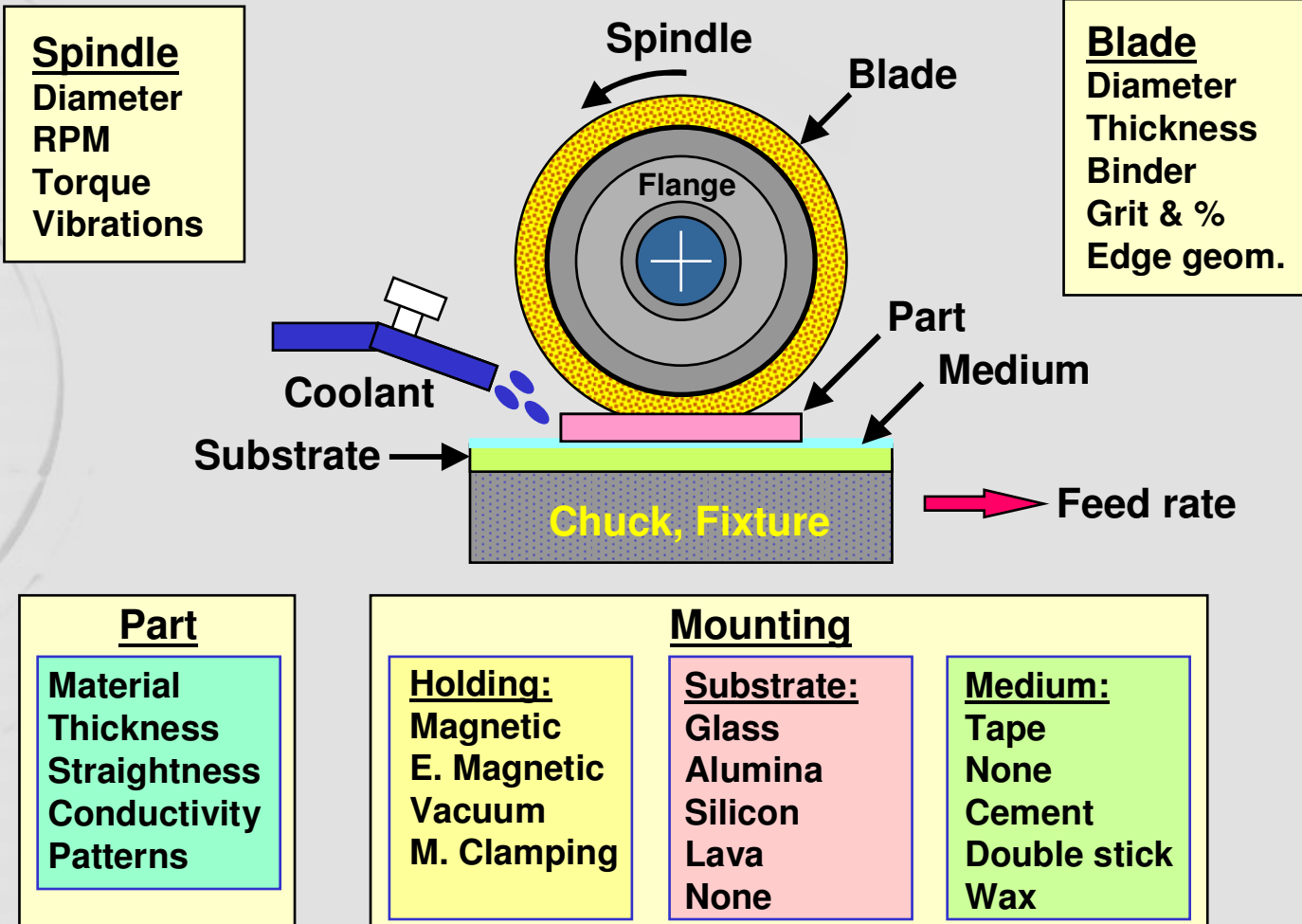




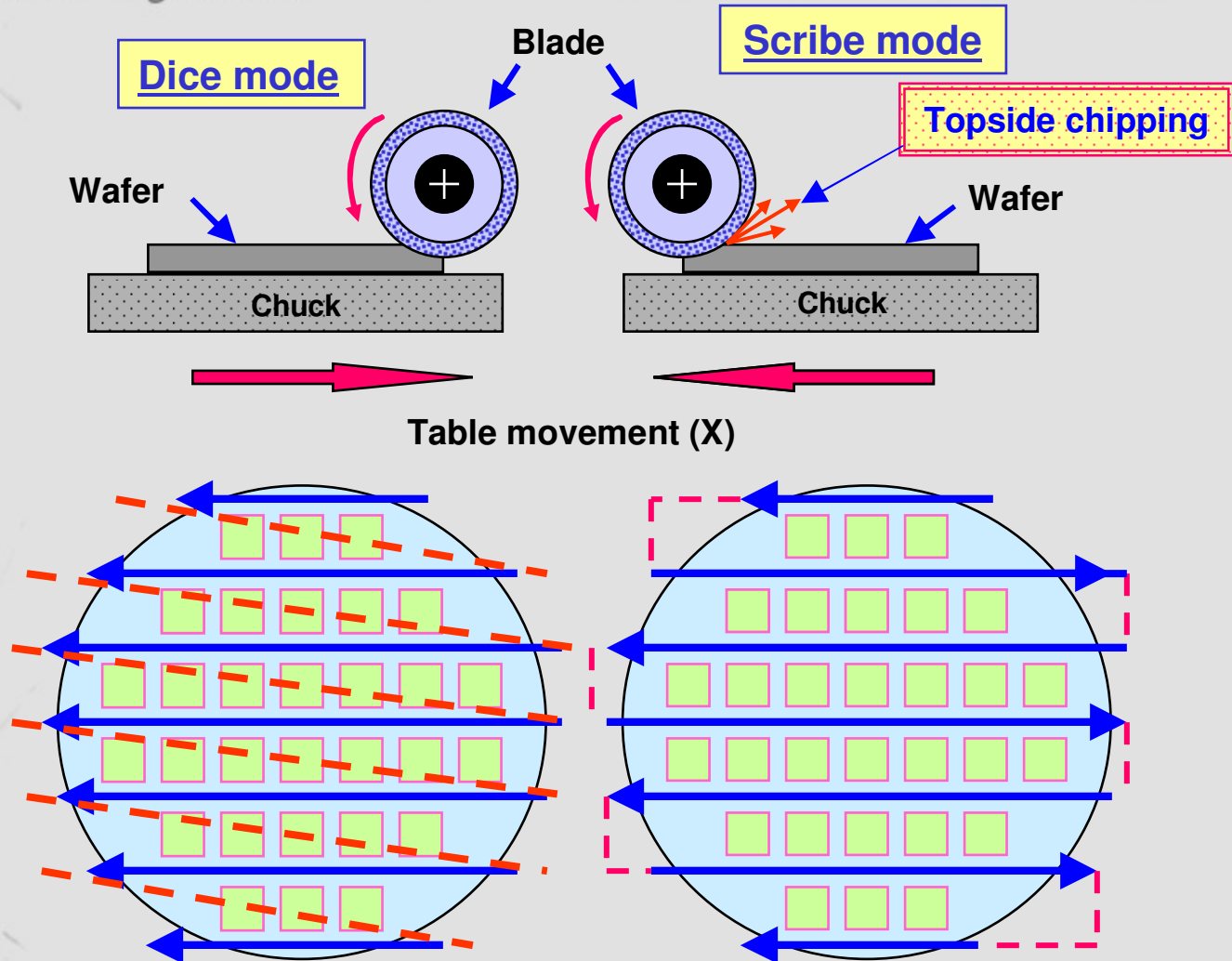
Process Techniques & Parameters

Process Techniques & Parameters

Application Characteristics

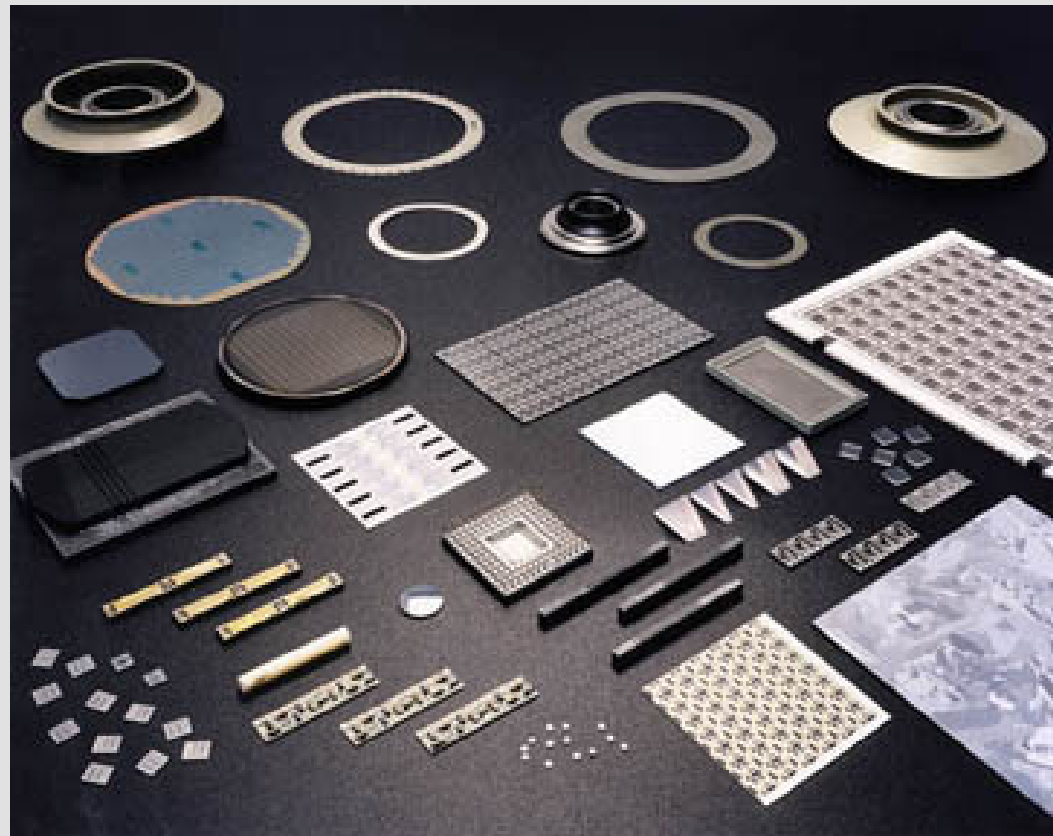


Cutting Mode



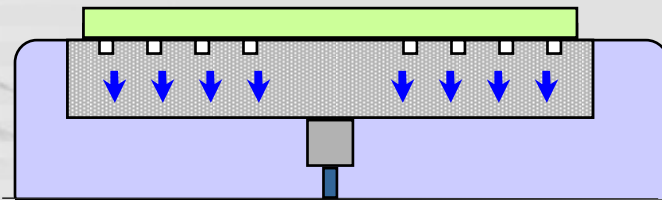


Application Characteristics

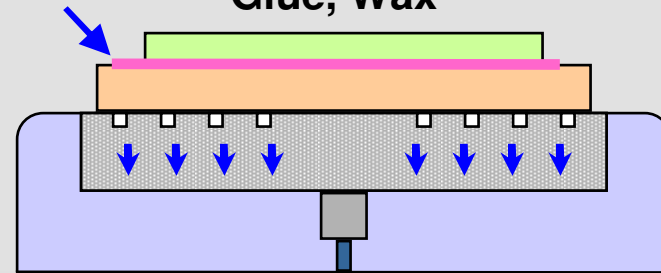


Mounting Methods

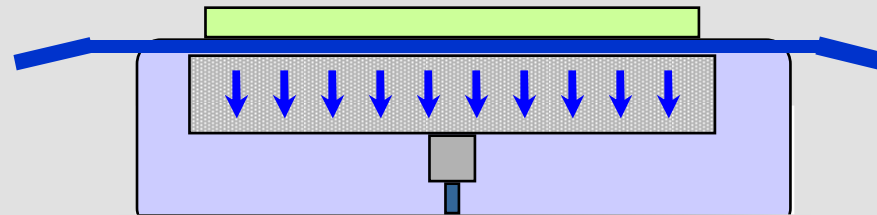
Vacuum (Ring chuck)



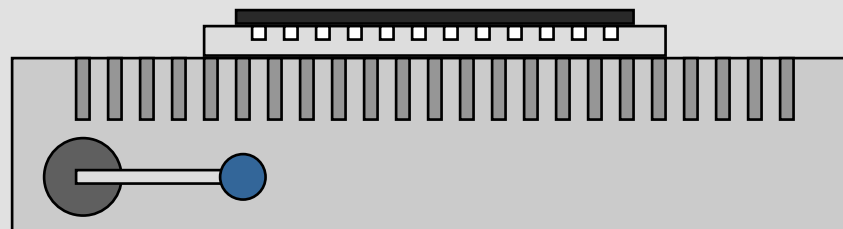
Glue, Wax



Tape on vacuum



- Magnetic**
- Mechanical
 - Electrical

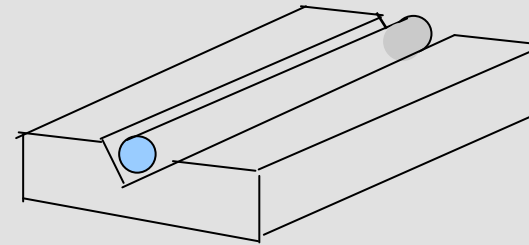
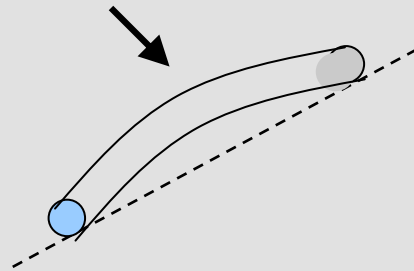


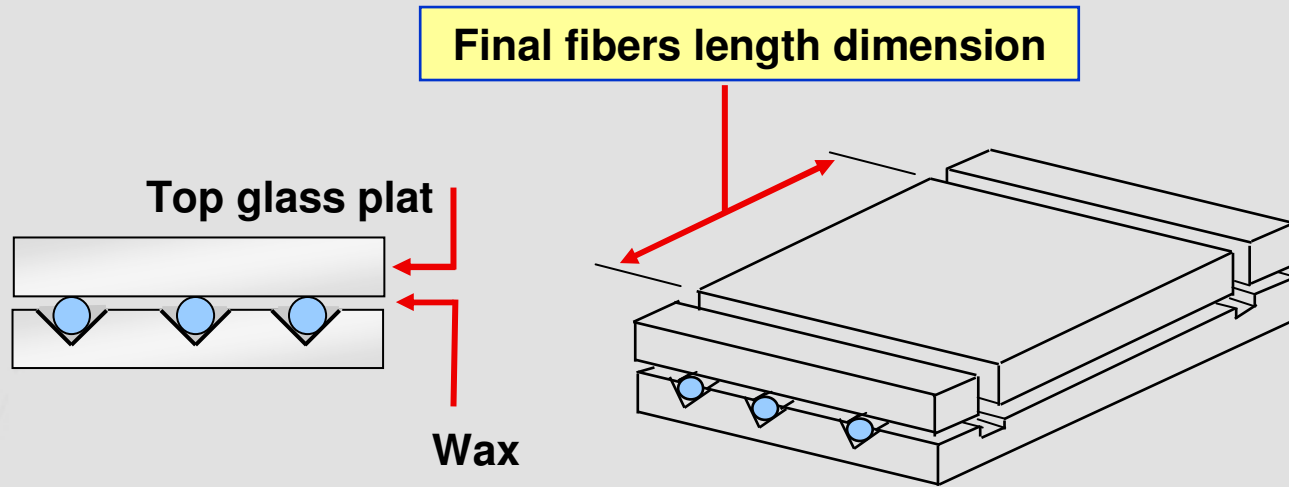


Special Clamping Methods

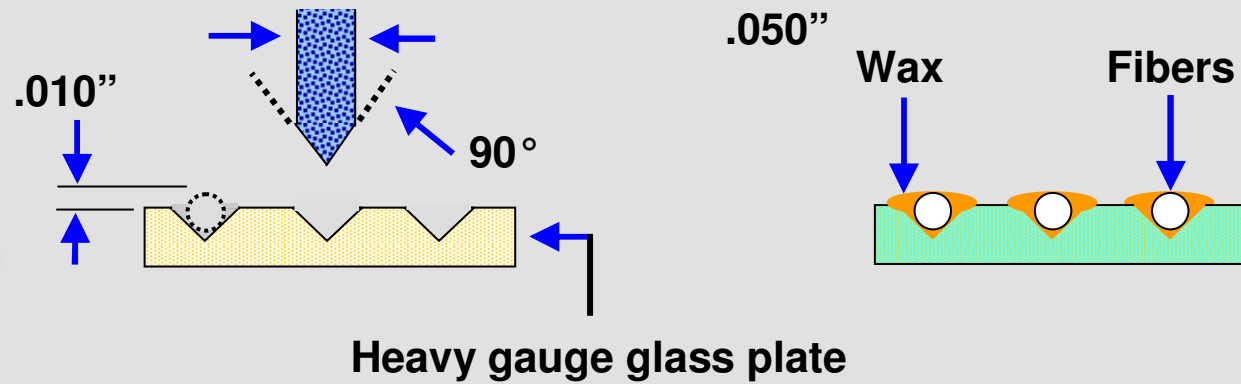


Fiber optic



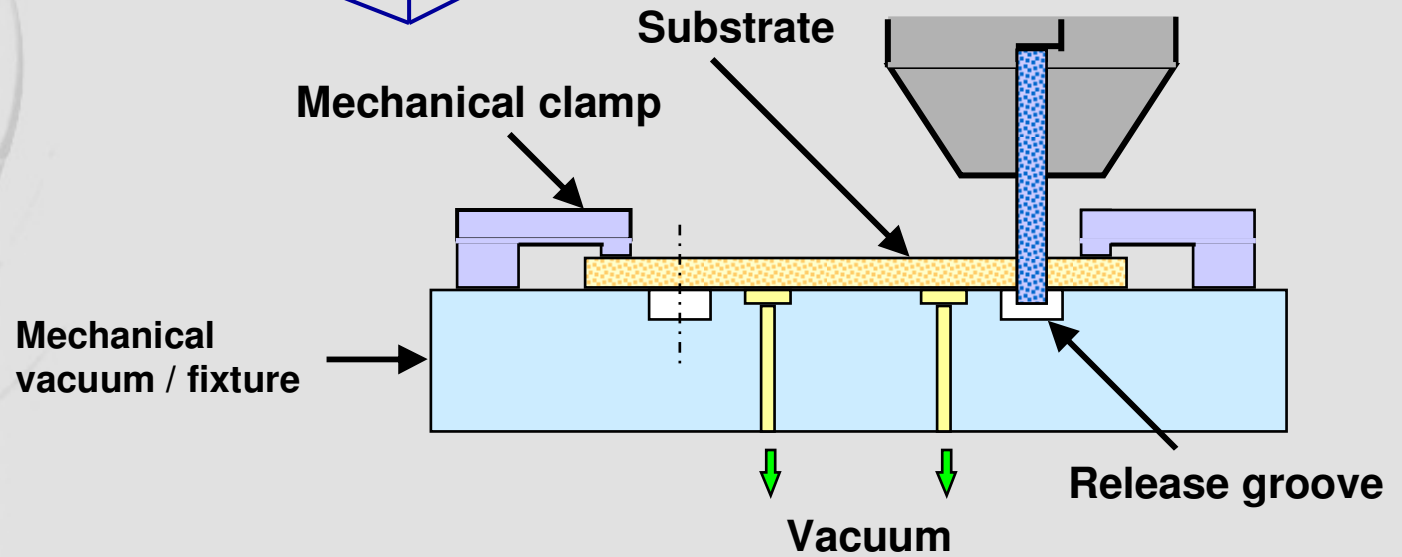
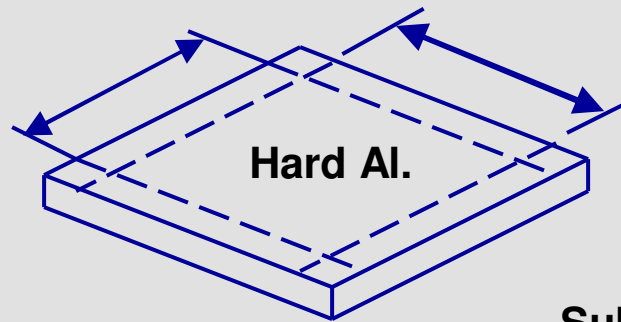


Special Clamping Methods



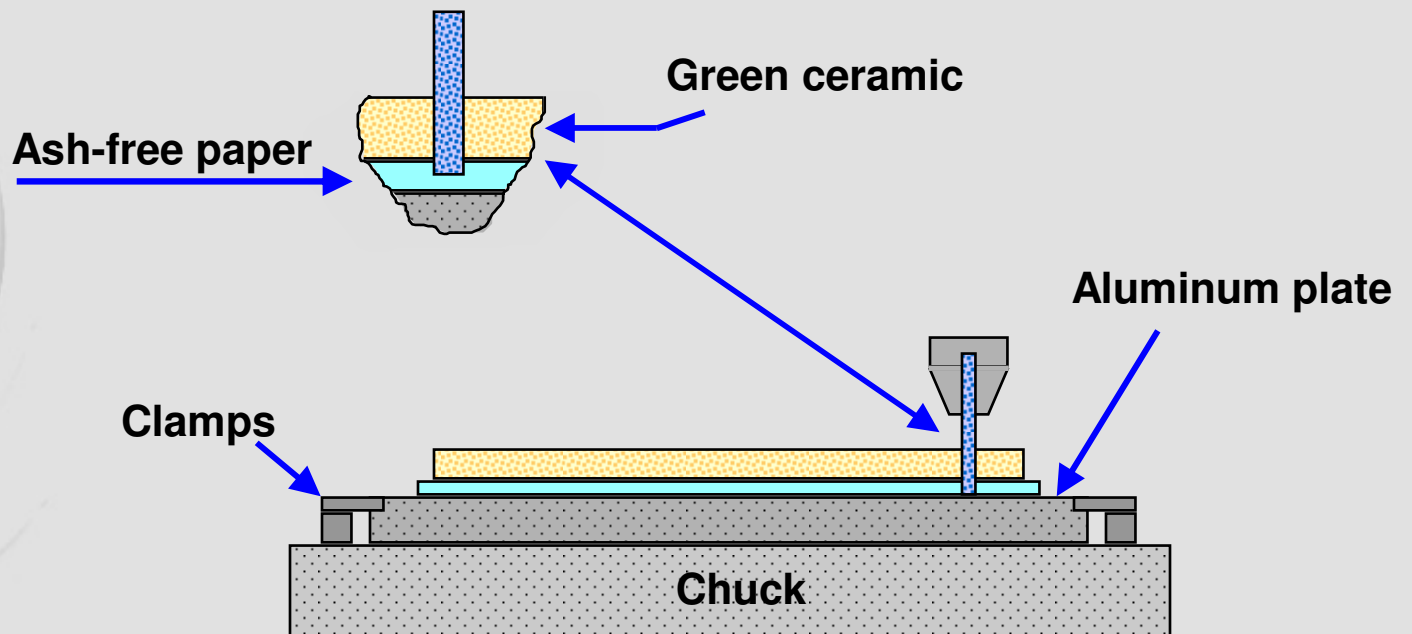
Special Mounting

Trimming 4 sides



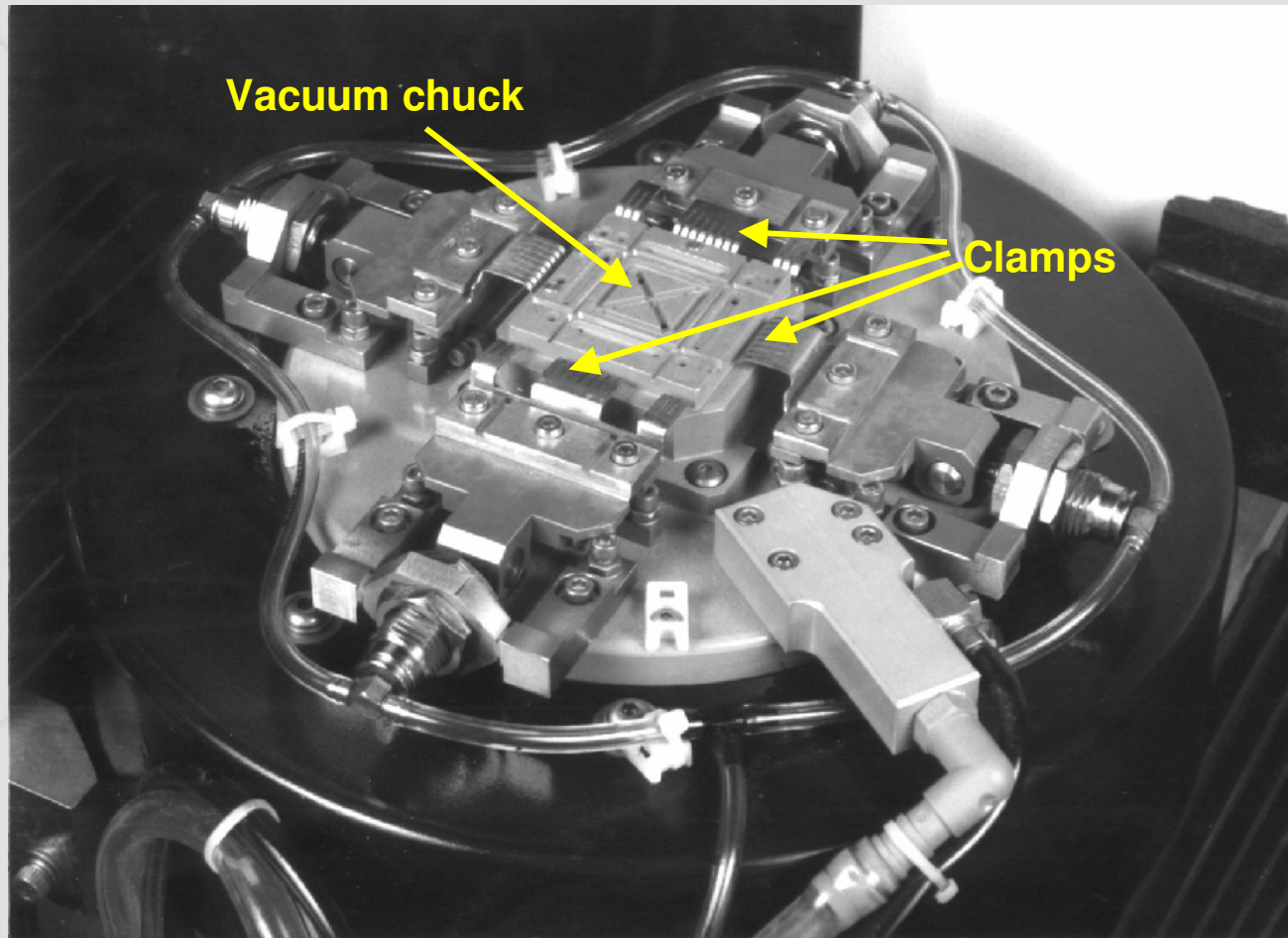
Special Clamping

**Mechanical / Laminated fixture on chuck
for MLC - Green Ceramic**

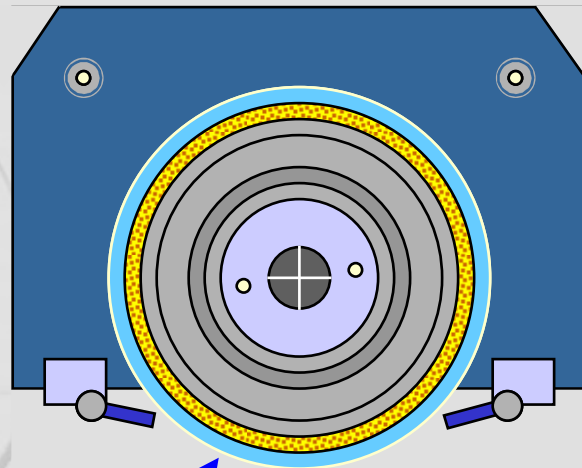




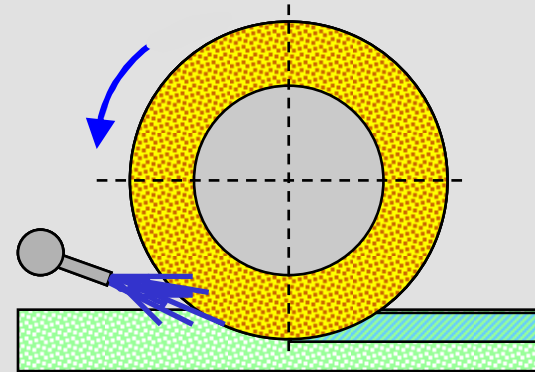
Special Clamping



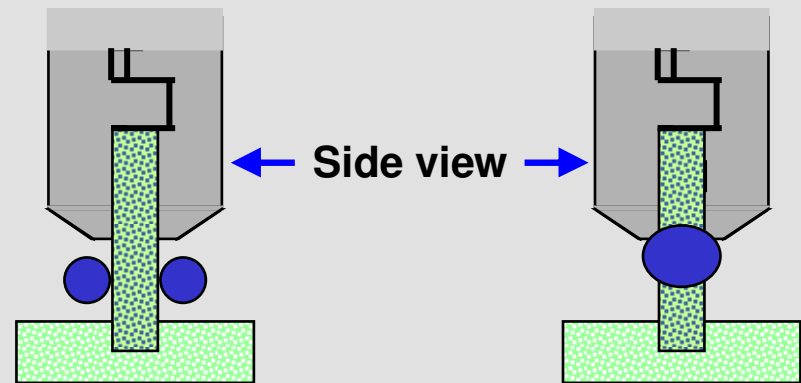
Blade Cooling



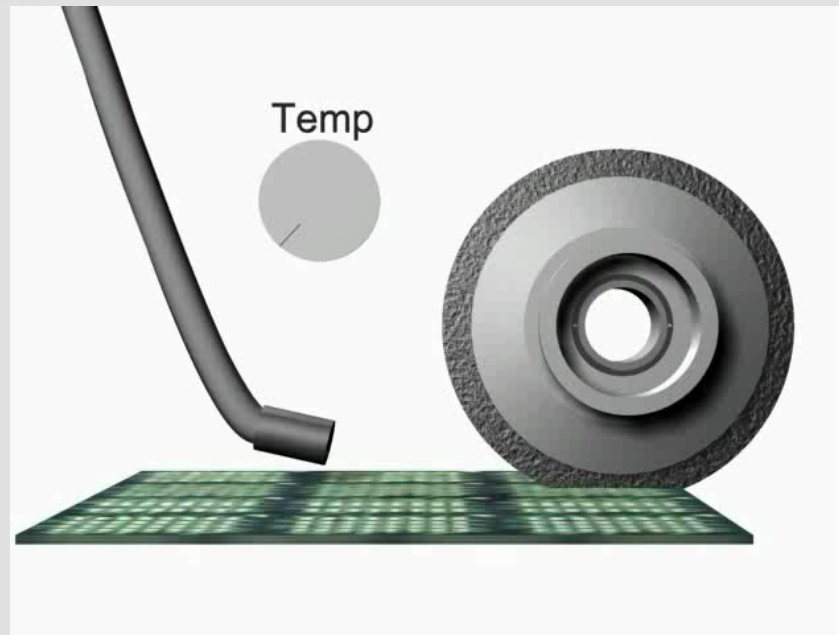
Air knife



Front view



Side view



- **Direction & Flow rate:**

- Main jet adjustment:

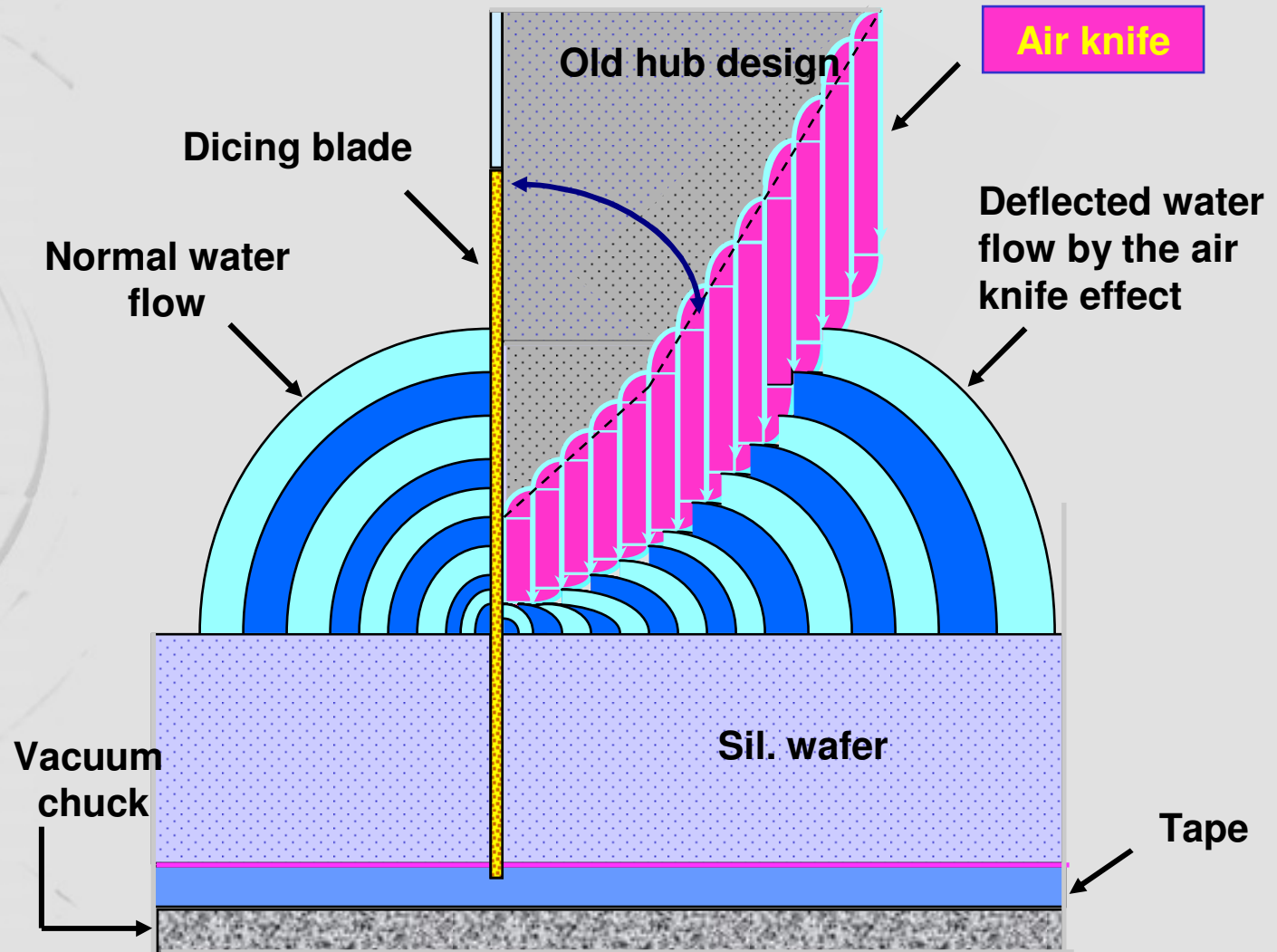
- Too low - does not provide effective cooling
 - Too high - may increase blade vibrations, blade straightness & poor substrate coolant
 - Too much pressure can lead to die lift off



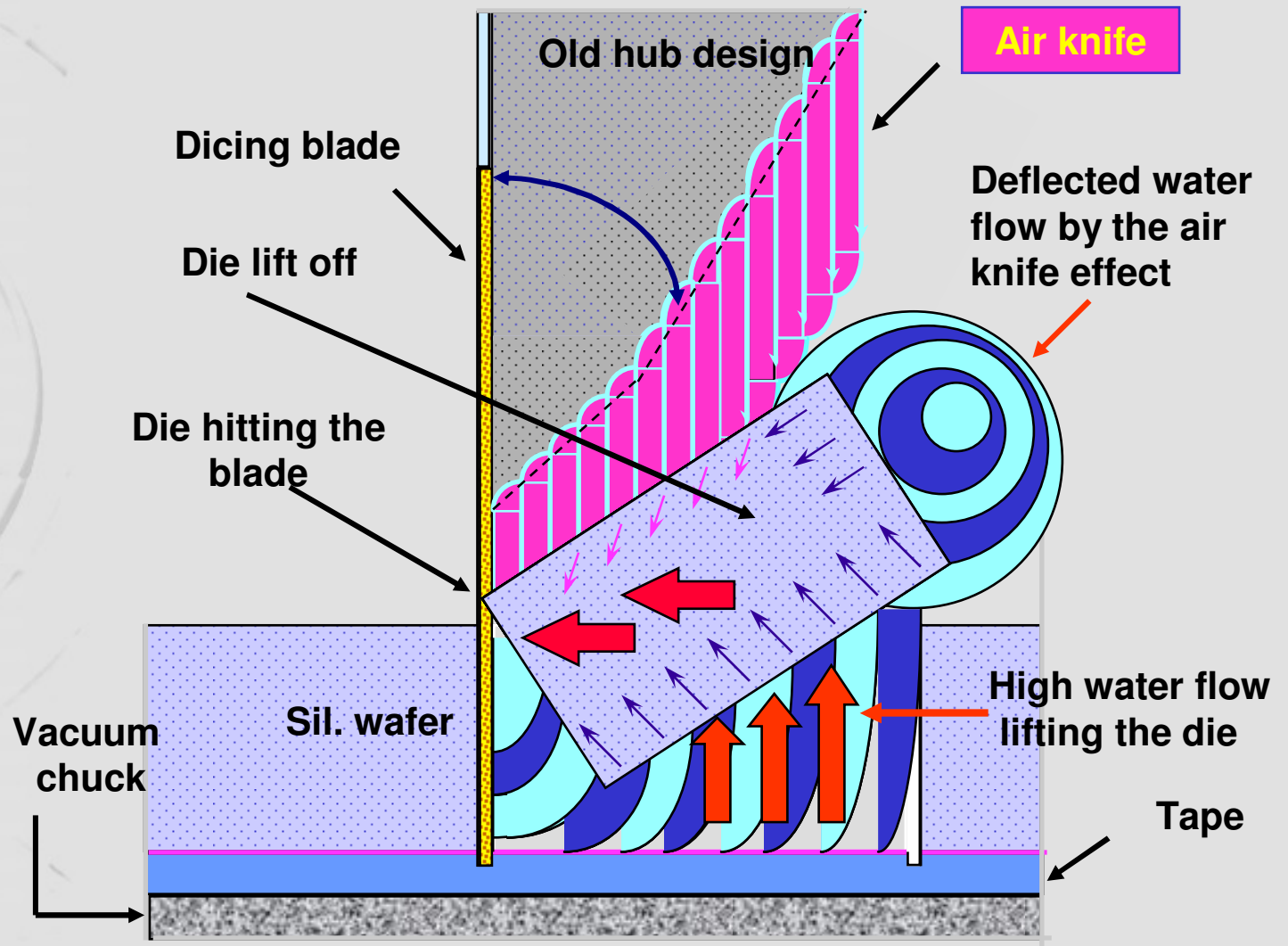
Coolant additives results in:

- Lowers the surface tension of the coolant for better coolant penetration.
- Minimizes the load
- Better washing of dicing dust

The Effect of Hub Geometry on the Coolant Flow



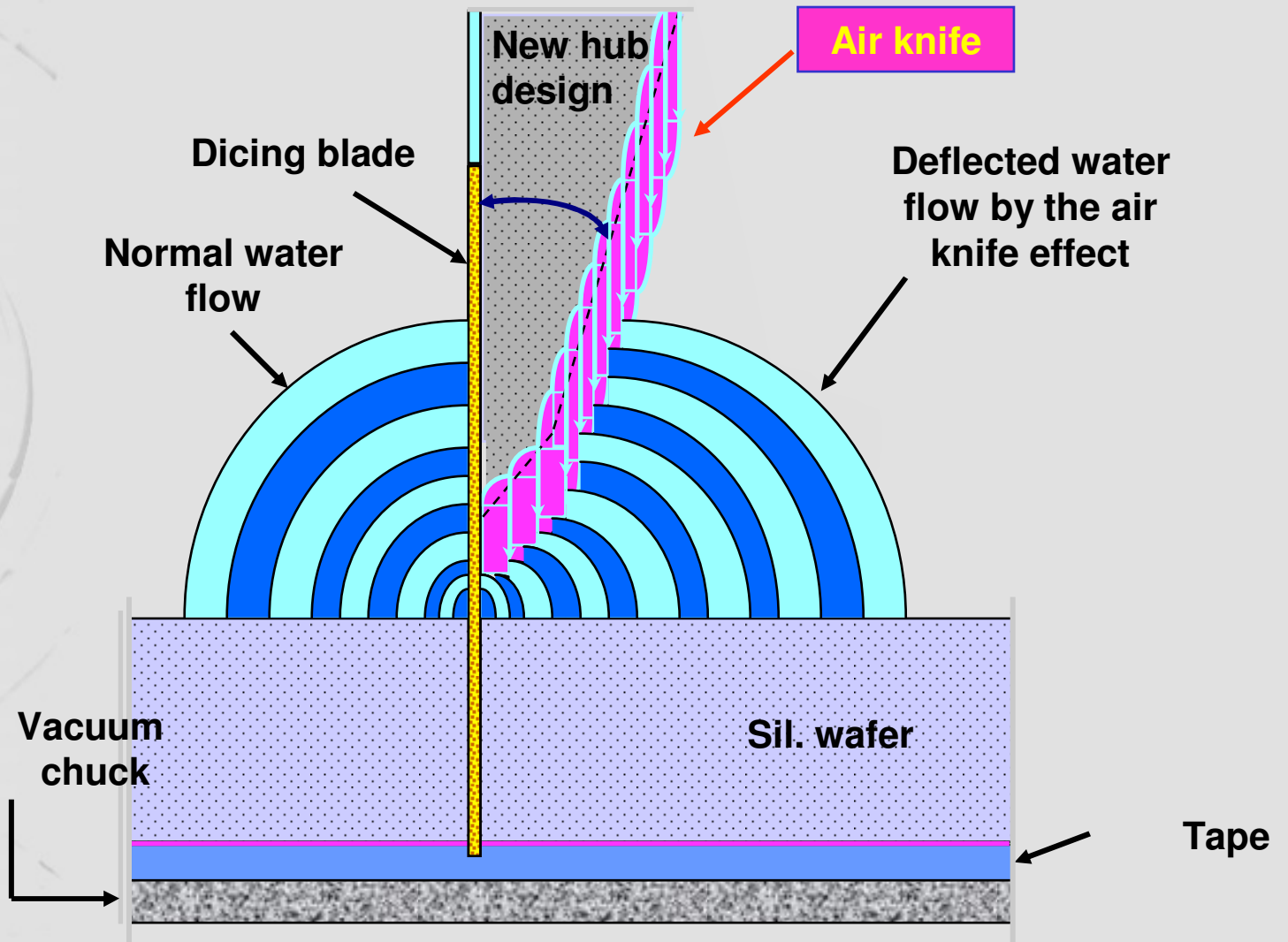
Effect of hub geometry on Die lift off / Blade Breakage



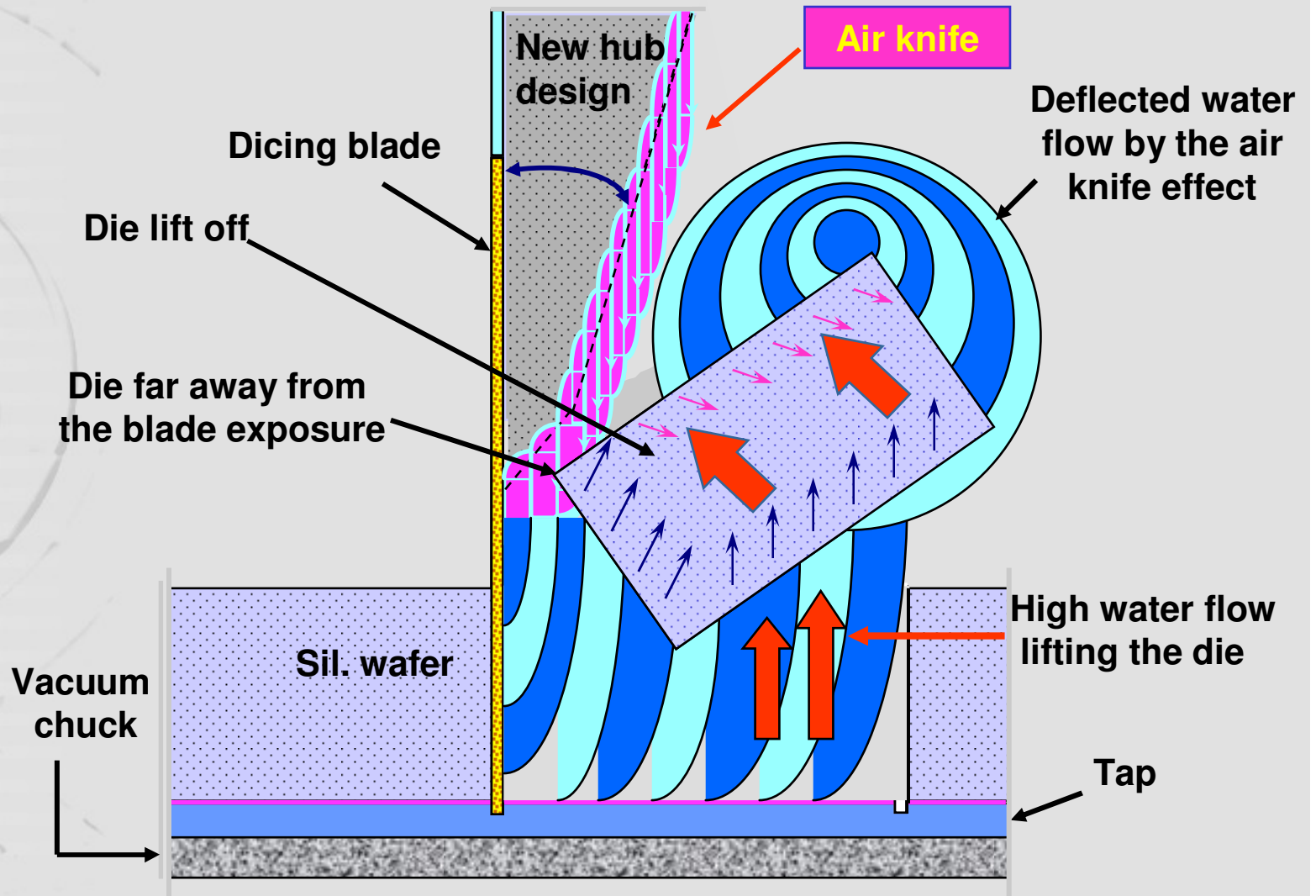


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The Effect of Hub Geometry on the Coolant flow



Effect of Hub Geometry on Die Lift off / Blade Breakage





Blade Characteristics

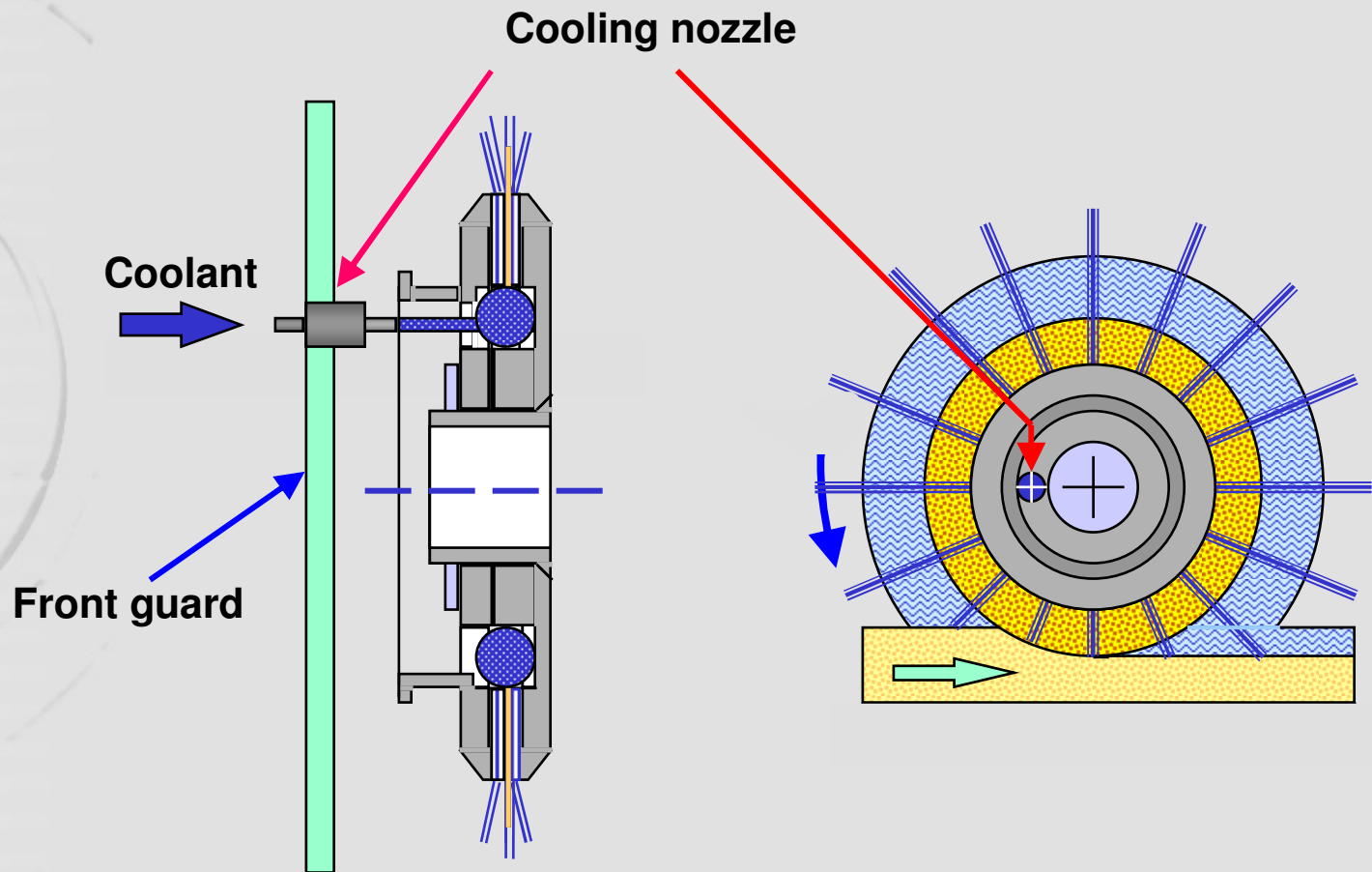
Green Ceramic diced with nickel serrated

**.6" thick Green Cer.
(M.L.C.) diced with a
5" O.D. nickel
serrated blade**



.6" Thick Green Ceramic Substrate
(M.L.C.) Diced with a 5" O.D.
Nickel Serrated Blade

High Cooling Flange set-up



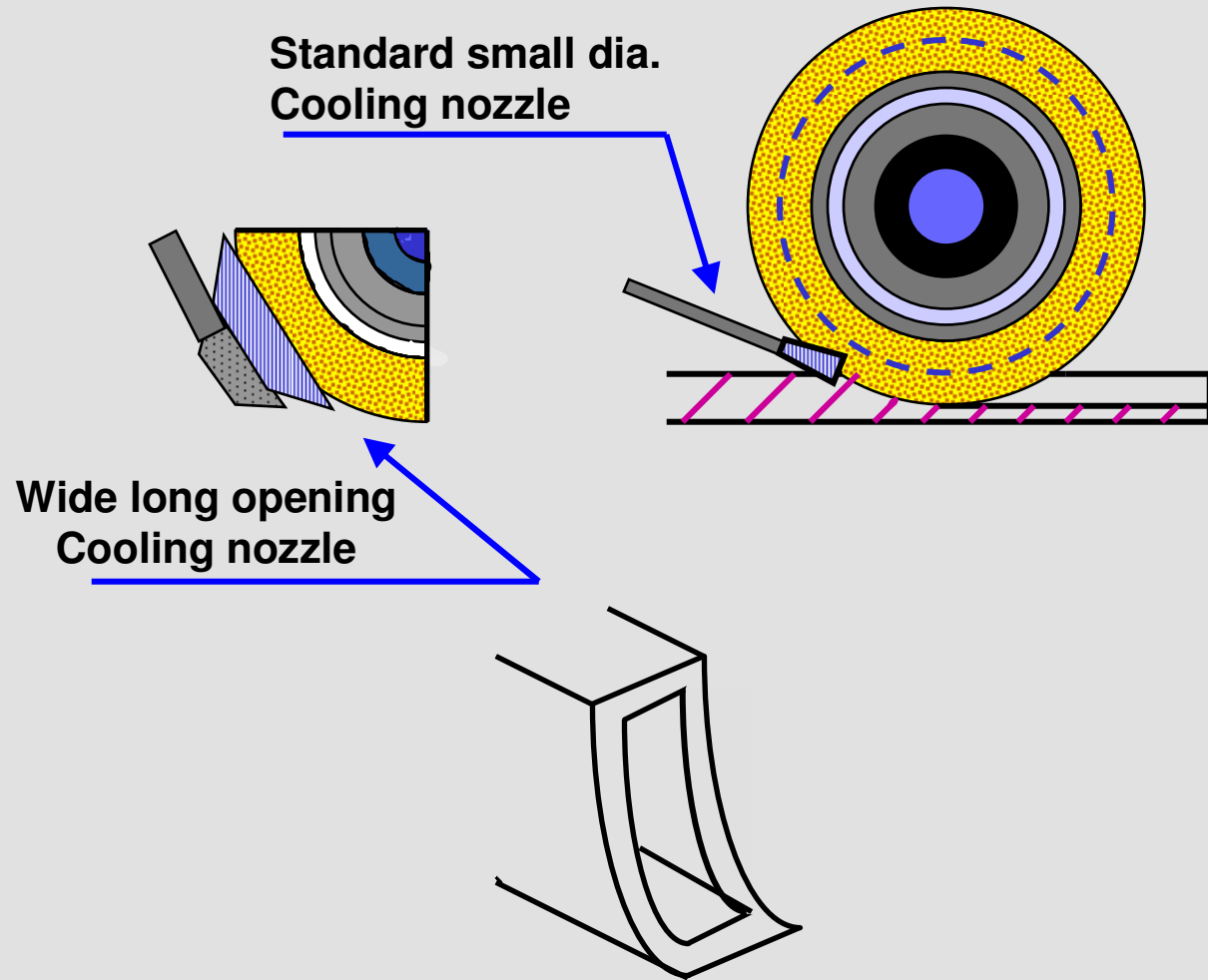


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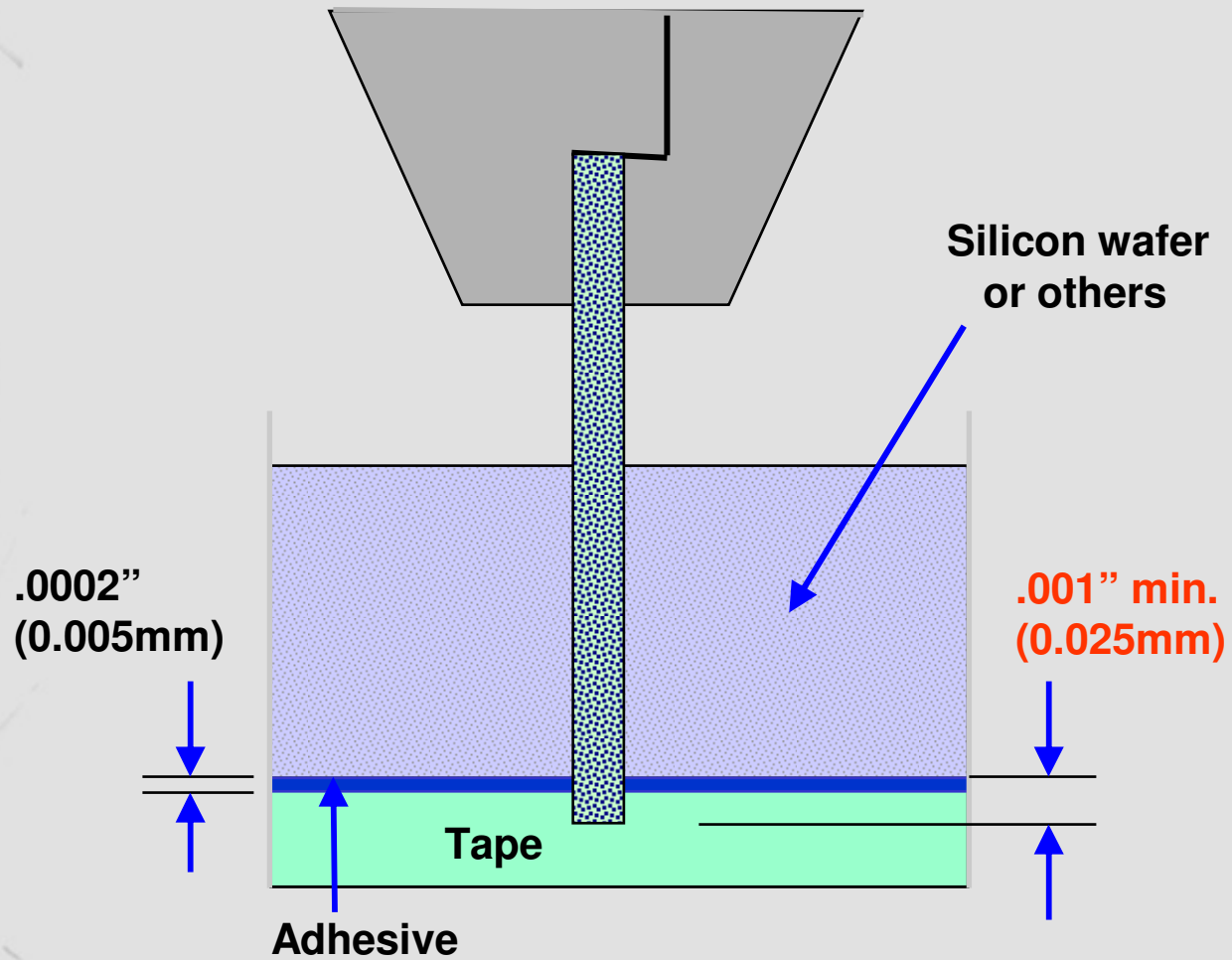
High Cooling Flange set-up



Blade Wear - Coolant Compensation



Cutting Through into Tape



Maximum Recommended Blade Exposure :

Nickel Blades

☛ Blade thickness X 30

Sintered Blades

☛ Blade thickness X 20

Resin Blades

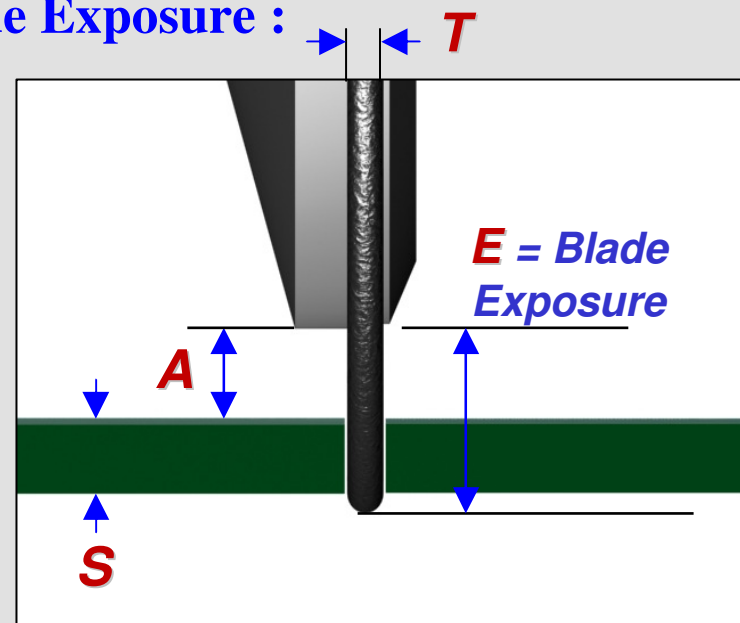
☛ Blade thickness X 10

$$E = A + S + T/2$$

A = min .300mm (12mil)

T = Blade Thickness

S = Substrate thickness

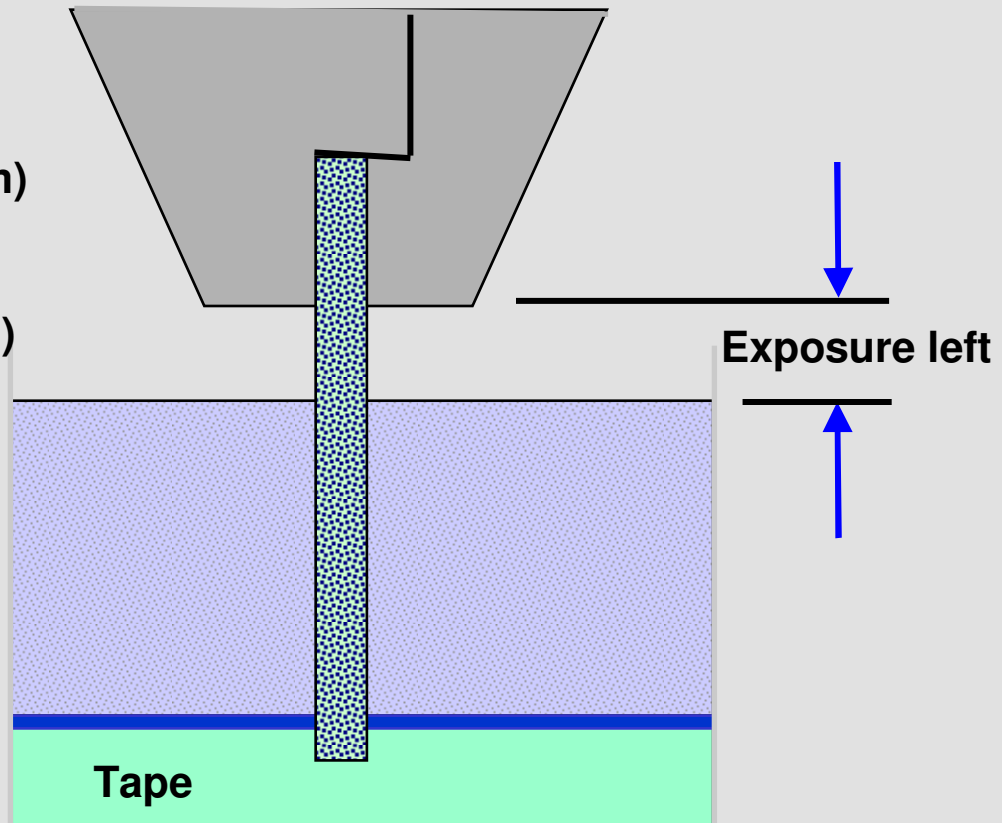


Exposure Left

Recommended exposure left on thin blades for Sil. application

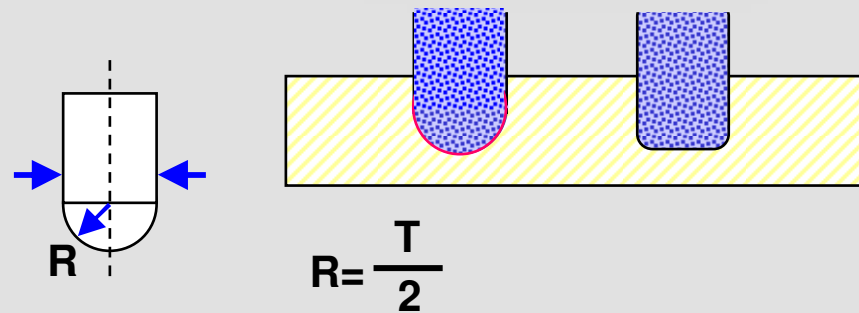
Min. Exp. Left
.005" (0.127mm)

Max Exp. Left
.010" (0.254mm)

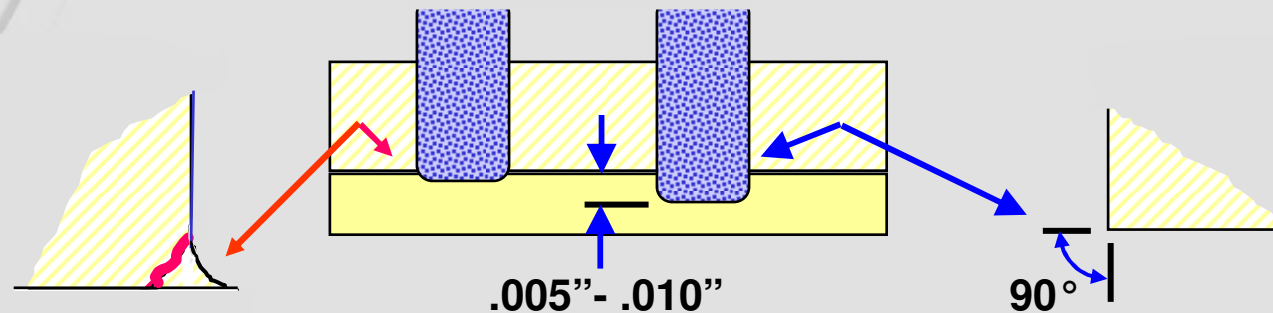


Cutting Through - Thick Substrate

The Theoretical max. radius on the blade edge =
50% of blade thickness

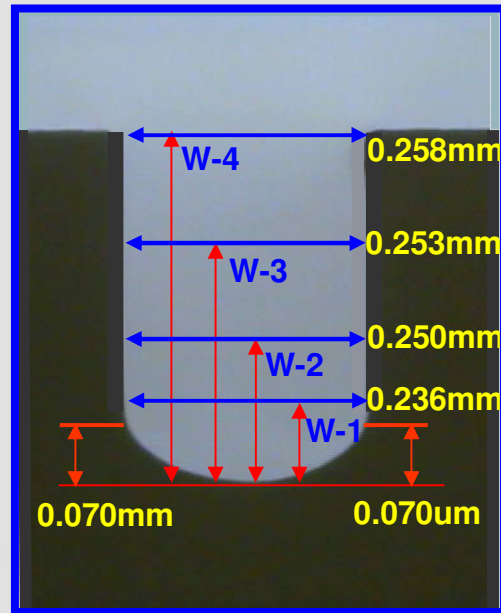


It is important to dice .005" - .010" (0.13-0.25mm)



A shallower cut will result in a lip effect at the back side
= Back side chipping & device size issues

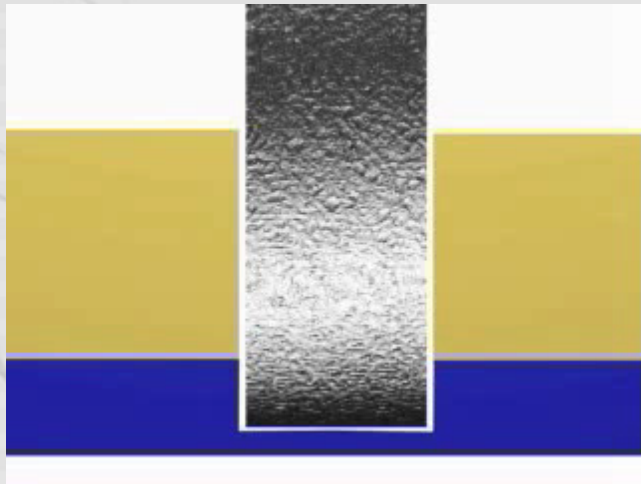
Kerf Profile Measurement



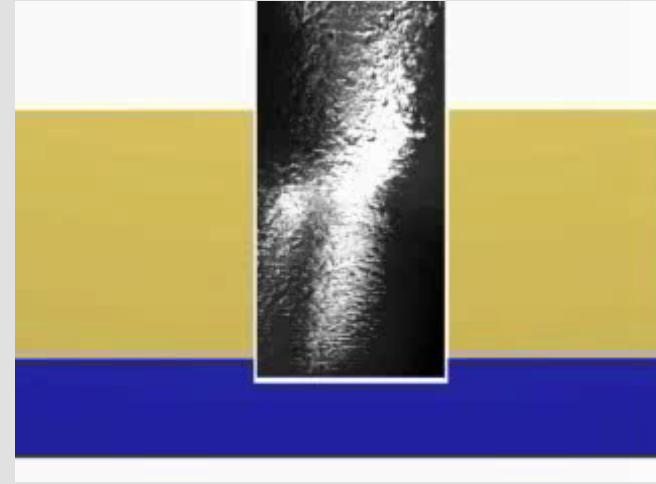
Measurement location	Kerf width um
W1=0.050	236
W2=0.075	250
W3=0.100	253
W4=0.300	258
Height	70/70
W4-W1	22
W4-W2	8
W4-W3	3

Process Parameters

Cut Depth into tape



Deeper cut



Shallow cut

- Deeper cut reduces blade radius affect.
- Optimum cut depth = $0.5 \times$ blade thickness.

Dicing Green Ceramic

Wet process:

Using nickel serrated blades 17, 30, 50 & 70mic. Grit
For better cut quality anon serrated blade can be used

Dry Process:

Using nickel blades and Tungsten carbides
(Same diamond grit as with the wet process)

Nickel blade:

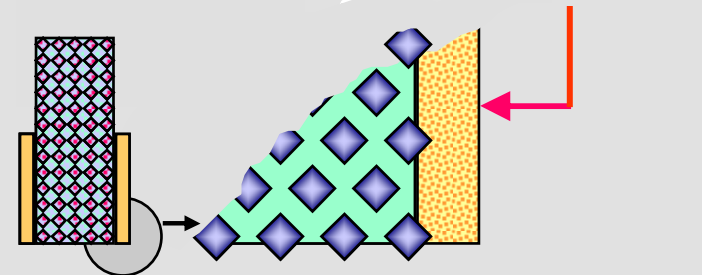
Advantages - Minimum blade wear
Easy handling
Availability

Disadvantages - Powder build-up
Extra blade cleaning is needed

Tungsten carbide blade:

Advantages - A cleaner cut in some applications

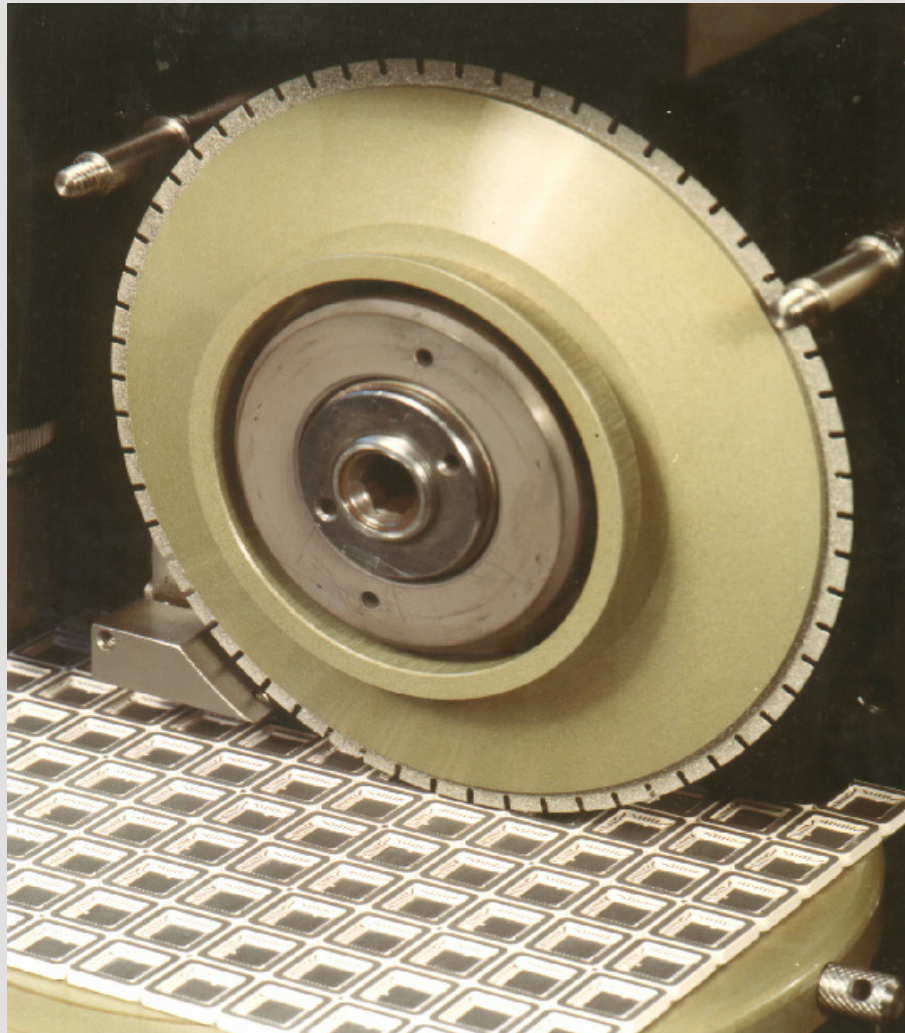
Disadvantages - Short life, poor availability, blade breakage





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Green Ceramic

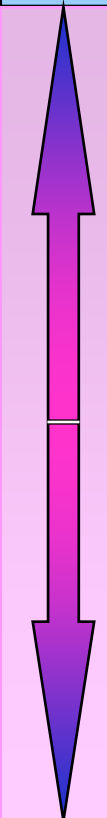




Dicing Seminar

Major Applications - Material Dicing Guide

Material Dicing Guide - Blade related

Material	Hardn.	Brittleness					Blade Matrix & Diamond Grit [mic.]					Remarks
	Hard	□	←	→	□	□	Resin , Grit	Nick., Grit	Sint. , Grit	□		
Sapphire						■	QKP	53,63	No		No	
Ruby						■	GWK	53,63	No		No	
Alumi. Nitride					■		KUP, RUP	63-105	No		No	
Alumina				■			KUP, RUP	45-63	No		No	Also with standard matrix
Titanium Car.				■			KUP, QKP	30-53	Yes	10-30	Yes	10-25
Kovar			■				AUP	53,63	No		No	
Quartz						■	QIP, KUP	30	No		No	
Glass / Pyrex						■	KUP, QIP	30,45	No		No	
PZT					■		AUP	9-45	Yes	3-6,10	No	
Barium Titan.						■	QUP, QKP	20-45	No		No	+ QIP Softer
Led Telluride						■			Yes	3-6	No	
Lithium Niob.						■	KUP, QUP	15-30	Yes	3-6	No	
Bismuth Telur.					■		RUP, KUP	45,53	Yes	17,30	No	
Silicon						■	QUP	9	Yes	4-6	No	
GaAs						■			Yes	2-4	No	
Ferrite						■	AUP, QIP	4-30	Yes	3-6,10	Yes	2-30
QFN		Soft	■				E06,T04&6	53-70	No		Yes	53



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Popular Resin Matrices

E- Series: E01, E03, E06
To minimize wear and improve cut quality on QFN

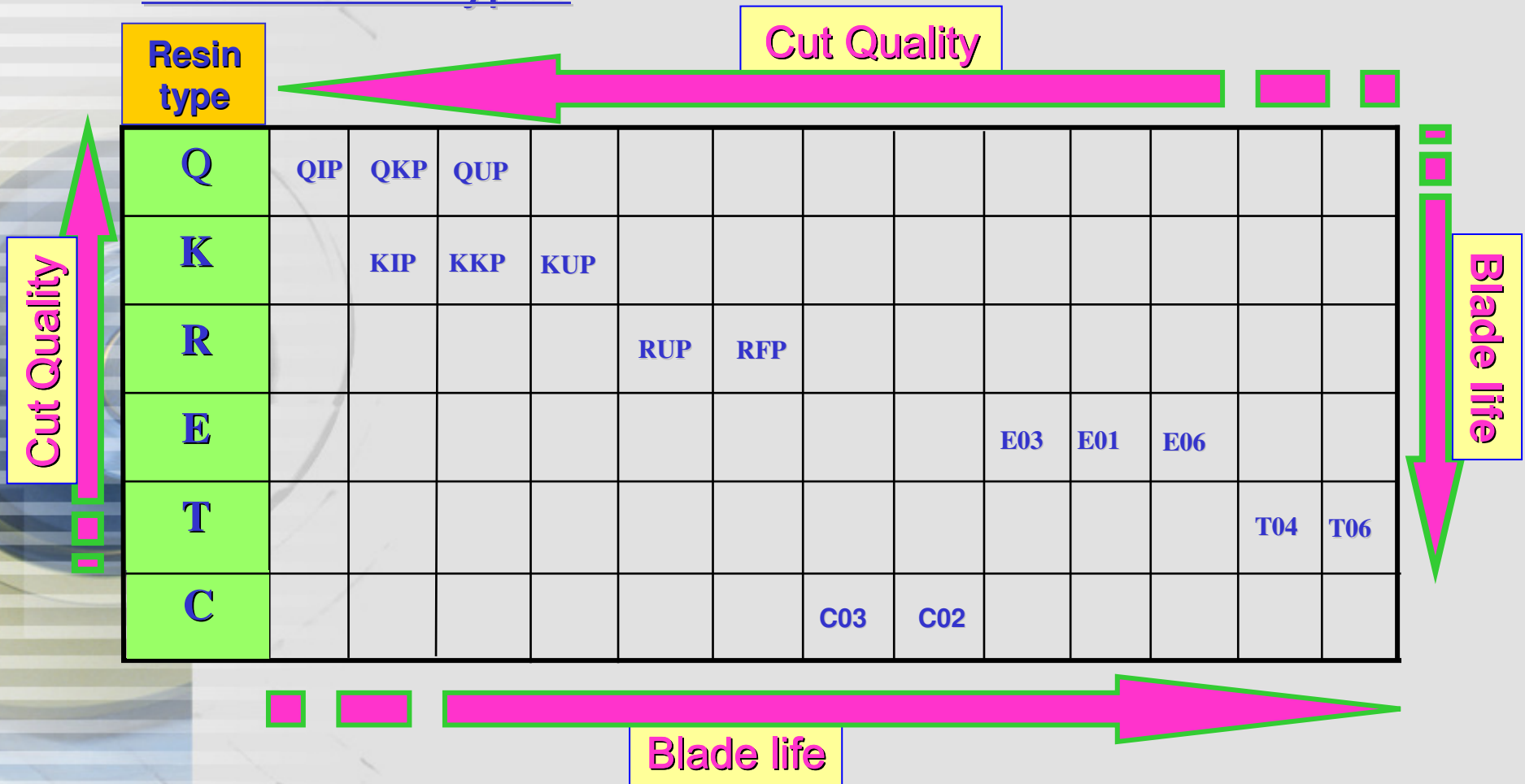
T- Series: T04 & T06
New developments for QFN

C- Matrices: C02 & C03
Improved wear and quality for hard Alumina

Matrix Code	Hardn.	Subst. Material	Remarks
Standard	↑	Hard Alumina and others.	Graphite Fib. Min. Wear.
RUP, RFP		Hard Al., some Glass, Bismuth Tel. Others	Best wear on new matrix.
KUP & KKP		-----"----- , Al. Nitr. T.Carbide, Lithium - Niobate, others.	Direct [First] replacement to our Standard m.
IUP		Same as above but thicker subst., more Loading.	Softer than KUP
QUP		Same subst.materials as KUP but more Brittle.	Will Minimize chipping.
QKP		Same subst. materials as KUP but more brittle & thicker.	Will minimize Chipping & loading.
QIP		Sapphire & Ruby	53 & 63mic grit
AUP		Quartz, Glass, Barium Titanate & other brittle mat.	Soft wearing mat. resulting in good edge quality.
AIP		PZT, some thicker Al. Kovar, some ferrites.	Soft resin but high dia. % For small grits.
			Hard materials Requiring high blade wear

Resinoid Blade Selection

Resin matrix types





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Material Dicing Guide - Blade related

Blade Type	Diamond size Micron	Product	Material
Nickel Blade	30,50,70	PBGA	FR4, Plastic & BT Resin
	6-8,10,17	PCB	FR4 & Copper
	3-6,10,17	Magnetic & Tape Heads	TiC & Ferrite
	2-4,4-8,10	Ultrasound Sensors	PZT
	2-4,3-6	Active Devices (Discrete)	GaAs
	4-8	SAW Devices	LiNbO3, LiTaO3
	2-4,3-6	IC's	Silicon
Steel Core Ni Blades	30,50,70	MLC (Multi Layer Capacitors)	Green Ceramic
	30,50	PBGA	FR4, Plastic & BT Resin
Resinoid Blades	53,88,105	CBGA	Alumina
	53,63,88	Ceramic Packages	Alumina
	75,88,105	QFN/MLP (F/C & H/E)	Copper + Resin
	15,20,30	SAW Devices	Quartz, LiNbO3, LiTaO3
	6,9	Tape for VTR	Ferrite
	30,45	Ink Jet Print Heads, Fiber Optics	Glass, Quartz
Sintered Blades	9,15,25	Magnetic Heads	TiC
	30,50	PBGA (Tape & Tapless application)	FR4, Plastic & BT Resin
	9,10,15	Fiber Optics	Glass, Quartz
	30,40,50	QFN/MLP (H/E)	Copper + Resin
	20,30,40	Ceramic Packages	Alumina



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Blade Selection

Recommended Values

Product	Material	Blade Type	Blade O.D	Matrix	Diamond size mic	Spindle Speed KRPM	Feed Rate	
							mm/s	Inch/s
PBGA	Epoxy & Molding	Sintered / Nickel	2"		30, 40, 50	2": 30-45	100-200	4-8
			3"			3": 20-30		
QFN	Cooper & Molding	Resin	2"	Resin: E type	88, 105, 125	2": 25-30	50-125	2-5
			3"			3": 15-28		
PCB	FR4 / Epoxy & Cooper	Nickel	2"	"T", "V", "Z"	10, 13, 17	2": 25-30	100-150	4-6
			4"			4": 15-28		
Ceramic Packages	Alumina	Resin	2"	* KUP, RUP	45,53, 63	18-28	4-20	0.15-0.8
			4"			10-18		
Multi Layer Capacitor	Green Ceramic	Nickel Steel Core	4"		30, 50, 70	12-18	100-250	4-10
Ultrasound Sensors	PZT	Nickel	2"		2-4, 4-8, 10	25-35	0.5-10	0.02-0.4
IC	Silicon	Nickel	2"		2-4, 3-6	30-50	25-75	1-3



Blade Selection

Recommended Values (cont.)

Product	Material	Blade Type	Blade O.D	Matrix	Diamond size mic	Spindle Speed KRPM	Feed Rate	
							mm/s	Inch/s
Optical and Electro-Optics components	Sapphire	Resin	2" 4"	* QIP , QKP , QUP	30, 45 ,53	16-20 8-10	1-10	0.04-0.4
Fiber Optics components	Quartz	Resin	2" 4"	* QIP , QKP , QUP	30, 45, 53	18-30 8-18	2-10	0.1-0.4
Fiber Optics components	Glass / Fused Silica	Resin	2" 4"	* QIP , QKP , QUP	30, 45, 53	16-30 8-18	2-10	0.1-0.4
Fiber Optics components	Si On Glass	Resin	2" 4"	* QIP , QKP , QUP	9, 15, 25	20-30 10-15	0.5-2.5	0.02-0.1
SAW Devices	Quartz	Resin	2" 4"	* QUP , KUP , RUP	30, 45, 53	18-30 8-18	2-10	0.1-0.4
SAW Devices	LiNbO3 ; LiTaO3	Nickel / Resin	2"	* QUP , KUP , RUP	Nickel: 4-8 Resin: 15, 20, 30	16-30	2-10	0.1-0.4
Tape Head	Ferrite	Resin / Nickel	2"	* QUP, KUP , RUP	Nickel: 3-6, 4-8, 10 Resin: 15, 20, 30	25-35	2-10	0.1-0.4
Magnetic Heads	AlTiCO3	Sintered / Nickel	4"		Sintered: 10, 17 Nickel: 3-6, 10, 15	Slicing: 8-12 Parting: 8-12	1-5 1-10	0.04-0.2 0.04-0.4



Maximum Recommended Spindle RPM - (*Safety - only*)

Nickel Blades:

2" O.D. - 40 - 60Krpm
3" O.D. - 35Krpm
4" O.D. - 30Krpm

M. Sintered:

2" O.D. - 40 - 60Krpm
3" O.D. - 35Krpm
4" O.D. - 30Krpm

Resinoid:

2" up to .015" thick - 35Krpm
2" .016" - .025" thick - 25Krpm
2" .026" - .035" thick - 20Krpm
3" up to .015" thick - 25Krpm
3" .016" - .025" thick - 22Krpm
3" .026" - .035" thick - 16Krpm
4" up to .015" thick - 16Krpm
4" .016" - .025" thick - 14Krpm
4" .026" - .035" thick - 12Krpm